

Microcontrollers



Never stop thinking.

Edition 2000-12

Published by Infineon Technologies AG, St.-Martin-Strasse 53, D-81541 München, Germany
© Infineon Technologies AG 2000.

All Rights Reserved.

Attention please!

The information herein is given to describe certain components and shall not be considered as warranted characteristics.

Terms of delivery and rights to technical change reserved.

We hereby disclaim any and all warranties, including but not limited to warranties of non-infringement, regarding circuits, descriptions and charts stated herein.

Infineon Technologies is an approved CECC manufacturer.

Information

For further information on technology, delivery terms and conditions and prices please contact your nearest Infineon Technologies Office in Germany or our Infineon Technologies Representatives worldwide (see address list).

Warnings

Due to technical requirements components may contain dangerous substances. For information on the types in question please contact your nearest Infineon Technologies Office.

Infineon Technologies Components may only be used in life-support devices or systems with the express written approval of Infineon Technologies, if a failure of such components can reasonably be expected to cause the failure of that life-support device or system, or to affect the safety or effectiveness of that device or system. Life support devices or systems are intended to be implanted in the human body, or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.

C505 C505C C505A C505CA

8-Bit Single-Chip Microcontroller

Microcontrollers



C505/C505C/C505A/C505CA Data Sheet Revision History: Current Version: 2000-12						
Previous Releases :		08.00, 06.00, 07.99, 12.97				
Page Page (in previous version Page (in current version)		Subjects (major changes since last revision)				
24	24	Version register VR2 for C505A-4R/C505CA-4R BB step is updated.				

Controller Area Network (CAN): License of Robert Bosch GmbH

We Listen to Your Comments

Any information within this document that you feel is wrong, unclear or missing at all? Your feedback will help us to continuously improve the quality of this document. Please send your proposal (including a reference to this document) to:

mcdocu.comments@infineon.com



8-Bit Single-Chip Microcontroller C500 Family

C505/C505C/C505A/ C505CA

Advance Information

- Fully compatible to standard 8051 microcontroller
- Superset of the 8051 architecture with 8 datapointers
- Up to 20 MHz operating frequency
 - 375 ns instruction cycle time @16 MHz
 - 300 ns instruction cycle time @20 MHz (50 % duty cycle)
- On-chip program memory (with optional memory protection)
 - C505(C)(A)-2R: 16K byte on-chip ROM
 - C505A-4R/C505CA-4R: 32K byte on-chip ROM
 - C505A-4E/C505CA-4E: 32K byte on-chip OTP
 - alternatively up to 64k byte external program memory
- 256 byte on-chip RAM
- On-chip XRAM
 - C505/C505C: 256 byteC505A/C505CA: 1K byte

(more features on next page)

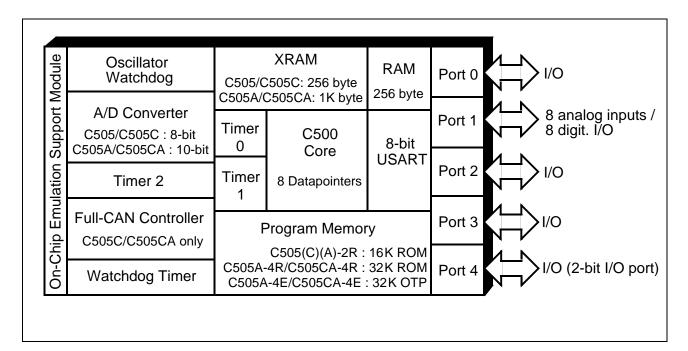


Figure 1 C505 Functional Units



Features (continued):

- 32 + 2 digital I/O lines
 - Four 8-bit digital I/O ports
 - One 2-bit digital I/O port (port 4)
 - Port 1 with mixed analog/digital I/O capability
- Three 16-bit timers/counters
 - Timer 0 / 1 (C501 compatible)
 - Timer 2 with 4 channels for 16-bit capture/compare operation
- Full duplex serial interface with programmable baudrate generator (USART)
- Full CAN Module, version 2.0 B compliant (C505C and C505CA only)
 - 256 register/data bytes located in external data memory area
 - 1 MBaud CAN baudrate when operating frequency is equal to or above 8 MHz
 - internal CAN clock prescaler when input frequency is over 10 MHz
- On-chip A/D Converter
 - up to 8 analog inputs
 - C505/C505C : 8-bit resolution
 - C505A/C505CA: 10-bit resolution
- Twelve interrupt sources with four priority levels
- On-chip emulation support logic (Enhanced Hooks Technology TM)
- Programmable 15-bit watchdog timer
- Oscillator watchdog
- Fast power on reset
- Power Saving Modes
 - Slow-down mode
 - Idle mode (can be combined with slow-down mode)
 - Software power-down mode with wake up capability through P3.2/INTO or P4.1/RXDC pin
- P-MQFP-44 package
- Pin configuration is compatible to C501, C504, C511/C513-family
- Temperature ranges:

SAB-C505 versions	$T_{A} = 0 \text{ to } 70 ^{\circ}C$
SAF-C505 versions	$T_{\rm A}$ = -40 to 85°C
SAH-C505 versions	$T_{\rm A}$ = -40 to 110°C
SAK-C505 versions	$T_{\rm A}$ = -40 to 125°C

Data Sheet 2 12.00



Table 1
Differences in Functionality of the C505 MCUs

Device	Internal Pro	ogram Memory	XRAM Size	A/D Converter	CAN
	ROM	ОТР		Resolution	Controller
C505-2R	16K byte	_	256 byte	8 Bit	_
C505-L	_	_	256 byte	8 Bit	_
C505C-2R	16K byte	_	256 byte	8 Bit	V
C505C-L	_	_	256 byte	8 Bit	V
C505A-4R	32K byte	_	1K byte	10 Bit	_
C505A-2R	16K byte	_	1K byte	10 Bit	_
C505A-L	_	_	1K byte	10 Bit	_
C505CA-4R	32K byte	_	1K byte	10 Bit	V
C505CA-2R	16K byte	_	1K byte	10 Bit	V
C505CA-L	_	_	1K byte	10 Bit	V
C505A-4E	_	32K byte	1K byte	10 Bit	_
C505CA-4E	_	32K byte	1K byte	10 Bit	V

Note: The term C505 refers to all versions described within this document unless otherwise noted. However the term C505 may also be restricted by the context to refer to only CAN-less derivatives with 8-Bit ADC which are C505-2R and C505-L in this document.

Note: The term C505(C)(A)-2R, for simplicity, is used to stand for C505 16K byte ROM versions within this document which are C505-2R, C505C-2R, C505A-2R and C505CA-2R.

Ordering Information

The ordering code for Infineon Technologies' microcontrollers provides an exact reference to the required product. This ordering code identifies:

- the derivative itself, i.e. its function set
- the specificed temperature rage
- the package and the type of delivery

For the available ordering codes for the C505 please refer to the "**Product information Microcontrollers**", which summarizes all available microcontroller variants.

Data Sheet 3 12.00



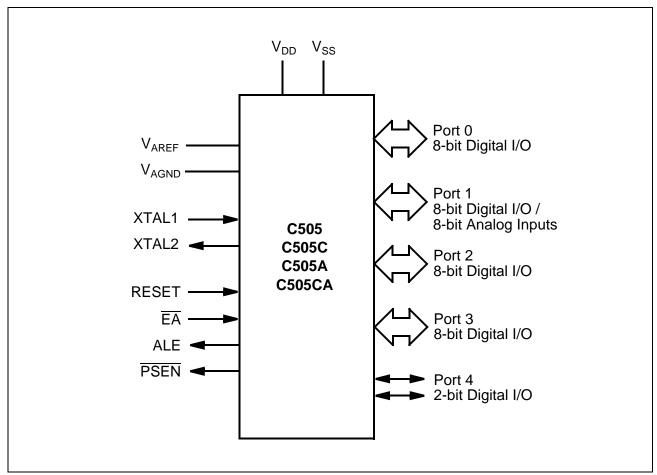


Figure 2 Logic Symbol

Note: The ordering codes for the Mask-ROM versions are defined for each product after verification of the respective ROM code.

Data Sheet 4 12.00



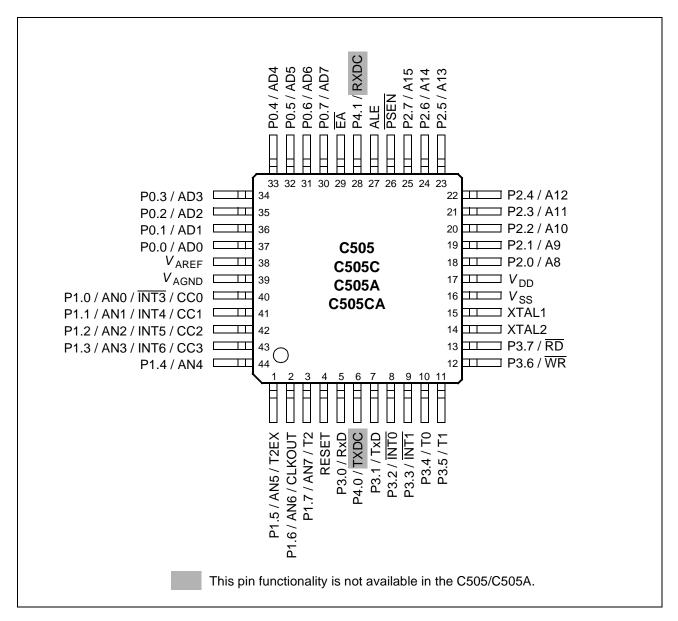


Figure 3
C505 Pin Configuration P-MQFP-44 Package (Top View)

Data Sheet 5 12.00



Table 2
Pin Definitions and Functions

Symbol	Pin Number	I/O *)	Function	
P1.0-P1.7	40-44,1-3	I/O	arrangement. Port 1 pins or as analog inputs of the have 1's written to them transistors and in that sinputs, port 1 pins being current (I_{IL} , in the DC internal pullup transistor used as analog inputs via As secondary digital functimer, clock, capture and corresponding to a sprogrammed to a one (1)	tions, port 1 contains the interrupt, d compare pins. The output latch secondary function must be for that function to operate (except). The secondary functions are
	40		P1.0 / AN0 / ĪNT3 / CC0	Analog input channel 0 interrupt 3 input / capture/compare channel 0 I/O
	41		P1.1 / AN1 / INT4 / CC1	Analog input channel 1/ interrupt 4 input / capture/compare channel 1 I/O
	42		P1.2 / AN2 / INT5 / CC2	•
	43		P1.3 / AN3 / INT6 / CC3	Analog input channel 3 interrupt 6 input / capture/compare channel 3 I/O
	44		P1.4 / AN4	Analog input channel 4
	1		P1.5 / AN5 / T2EX	Analog input channel 5 / Timer 2 external reload / trigger input
	2		P1.6 / AN6 / CLKOUT	Analog input channel 6 / system clock output
	3		P1.7 / AN7 / T2	Analog input channel 7 / counter 2 input
				order address byte during program COM versions (i.e. C505(C)(A)-2R/

^{*)} I = Input

O= Output

Data Sheet 6 12.00



Table 2
Pin Definitions and Functions (cont'd)

Symbol	Pin Number	I/O *)	Function		
RESET	4	I	RESET A high level on this pin for two machine cycle while the oscillator is running resets the device. An internal diffused resistor to $V_{\rm SS}$ permits power-on reset using only an external capacitor to $V_{\rm DD}$.		
P3.0-P3.7	5, 7-13 5 7 8 9	I/O	Port 3 is an 8-bit qual arrangement. Find pulled high by state can be use externally pulled characteristics. The output late must be program (except for Tx)	asi-bidirectional port with internal pull-up Port 3 pins that have 1's written to them are the internal pull-up transistors and in that sed as inputs. As inputs, port 3 pins being ed low will source current (I _{IL} , in the DC because of the internal pullup transistors. In corresponding to a secondary function med to a one (1) for that function to operate D and WR). The secondary functions are pins of port 3 as follows: Receiver data input (asynch.) or data input/output (synch.) of serial interface Transmitter data output (asynch.) or clock output (synch.) of serial interface External interrupt 0 input / timer 0 gate control input	
	10		control input P3.4 / T0 Timer 0 counter input		
	11 12		P3.5 / T1 P3.6 / WR	Timer 1 counter input WR control output; latches the data byte from port 0 into the external data memory	
	13		P3.7 / RD	RD control output; enables the external data memory	

^{*)} I = Input O= Output

Data Sheet 7 12.00



Table 2
Pin Definitions and Functions (cont'd)

Symbol	Pin Number	I/O *)	Function	
P4.0 P4.1	6 28	I/O I/O	Port 4 is a 2-bit quasi-bidirectional port with internal pull-up arrangement. Port 4 pins that have 1's written to them are pulled high by the internal pull-up transistors and in that state can be used as inputs. As inputs, port 4 pins being externally pulled low will source current ($I_{\rm IL}$, in the DC characteristics) because of the internal pullup transistors. The output latch corresponding to the secondary function RXDC must be programmed to a one (1) for that function to operate. The secondary functions are assigned to the two pins of port 4 as follows (C505C and C505CA only): P4.0 / TXDC Transmitter output of CAN controller P4.1 / RXDC Receiver input of CAN controller	
XTAL2	14	0	XTAL2 Output of the inverting oscillator amplifier.	
XTAL1	15	I	XTAL1 Input to the inverting oscillator amplifier and input to the internal clock generator circuits. To drive the device from an external clock source, XTAL1 should be driven, while XTAL2 is left unconnected. To operate above a frequency of 16 MHz, a duty cycle of the etxernal clock signal of 50 % should be maintained. Minimum and maximum high and low times as well as rise/fall times specified in the AC characteristics must be observed.	

^{*)} I = Input O= Output

Data Sheet 8 12.00



Table 2
Pin Definitions and Functions (cont'd)

Symbol	Pin Number	I/O *)	Function	
P2.0-P2.7	18-25	I/O	is a an 8-bit quasi-bidirectional I/O port with internal pullup resistors. Port 2 pins that have 1's written to them are pulled high by the internal pullup resistors, and in that state can be used as inputs. As inputs, port 2 pins being externally pulled low will source current (<i>I</i> _{IL} , in the DC characteristics) because of the internal pullup resistors. Port 2 emits the high-order address byte during fetches from external program memory and during accesses to external data memory that use 16-bit addresses (MOVX @DPTR). In this application it uses strong internal pullup transistors when issuing 1s. During accesses to external data memory that use 8-bit addresses (MOVX @Ri), port 2 issues the contents of the P2 special function register and uses only the internal pullup resistors.	
PSEN	26	0	The Program Store Enable output is a control signal that enables the external program memory to the bus during external fetch operations. It is activated every three oscillator periods except during external data memory accesses. Remains high during internal program execution. This pin should not be driven during reset operation.	
ALE	27	0	The Address Latch Enable output is used for latching the low-byte of the address into external memory during normal operation. It is activated every three oscillator periods except during an external data memory access. When instructions are executed from internal ROM or OTP (EA=1) the ALE generation can be disabled by bit EALE in SFR SYSCON. ALE should not be driven during reset operation.	

^{*)} I = Input O= Output

Data Sheet 9 12.00



Table 2
Pin Definitions and Functions (cont'd)

Symbol	Pin Number	I/O *)	Function
ĒĀ	29	I	External Access Enable When held at high level, instructions are fetched from the internal program memory when the PC is less than 4000 _H (C505(C)(A)-2R) or 8000 _H (C505A-4R/C505CA-4R/C505A-4E/C505CA-4E). When held at low level, the C505 fetches all instructions from external program memory. For the C505 romless versions (i.e. C505-L, C505C-L, C505A-L and C505CA-L) this pin must be tied low. For the ROM protection version EA pin is latched during reset.
P0.0-P0.7	37-30	I/O	is an 8-bit open-drain bidirectional I/O port. Port 0 pins that have 1's written to them float, and in that state can be used as high-impendance inputs. Port 0 is also the multiplexed low-order address and data bus during accesses to external program or data memory. In this application it uses strong internal pullup transistors when issuing 1's. Port 0 also outputs the code bytes during program verification in the C505 ROM versions. External pullup resistors are required during program verification.
V_{AREF}	38	_	Reference voltage for the A/D converter.
V_{AGND}	39	_	Reference ground for the A/D converter.
V_{SS}	16	_	Ground (0V)
V_{DD}	17	_	Power Supply (+5V)

^{*)} I = Input O= Output

Data Sheet 10 12.00



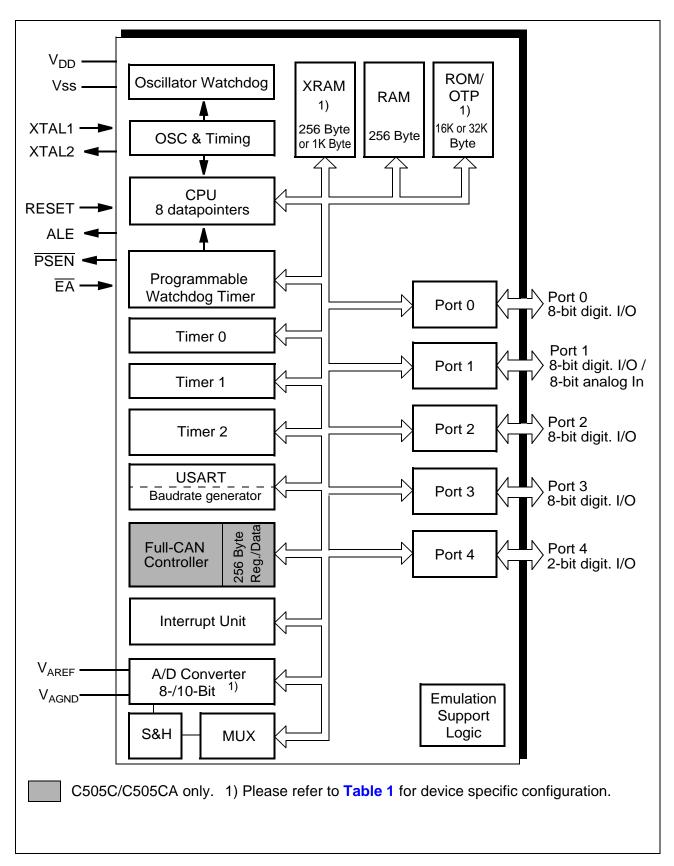


Figure 4
Block Diagram of the C505/C505C/C505A/C505CA

Data Sheet 11 12.00

Reset Value: 00H



CPU

The C505 is efficient both as a controller and as an arithmetic processor. It has extensive facilities for binary and BCD arithmetic and excels in its bit-handling capabilities. Efficient use of program memory results from an instruction set consisting of 44 % one-byte, 41 % two-byte, and 15% three-byte instructions. With a 16 MHz crystal, 58% of the instructions are executed in 375 ns (20MHz: 300 ns).

Special Function Register PSW (Address D0_H)

Bit No.	MSB	MSB							
		D6 _H							
D0 _H	CY	AC	F0	RS1	RS0	OV	F1	Р	PSW

Bit	Function	Function					
CY		Carry Flag Used by arithmetic instruction.					
AC		/ Carry Fla	g s which execute BCD operations.				
F0	General	Purpose F	Flag				
RS1 RS0		Register Bank Select Control Bits These bits are used to select one of the four register banks.					
	RS1	RS0	Function				
	0	0	Bank 0 selected, data address 00 _H -07 _H				
	0	1	Bank 1 selected, data address 08 _H -0F _H				
	1	0	Bank 2 selected, data address 10 _H -17 _H				
	1	1	Bank 3 selected, data address 18 _H -1F _H				
OV		Overflow Flag Used by arithmetic instruction.					
F1	General	General Purpose Flag					
Р	Set/clear	Parity Flag Set/cleared by hardware after each instruction to indicate an odd/even number of "one" bits in the accumulator, i.e. even parity.					

Data Sheet 12 12.00



Memory Organization

The C505 CPU manipulates operands in the following four address spaces:

- On-chip program memory :16K byte ROM (C505(C)(A)-2R) or 32K byte ROM (C505A-4R/C505CA-4R) or 32K byte OTP (C505A-4E/C505CA-4E)
- Totally up to 64K byte internal/external program memory
- up to 64 Kbyte of external data memory
- 256 bytes of internal data memory
- Internal XRAM data memory :256 byte (C505/C505C)
 1K byte (C505A/C505CA)
- a 128 byte special function register area

Figure 5 illustrates the memory address spaces of the C505 versions.

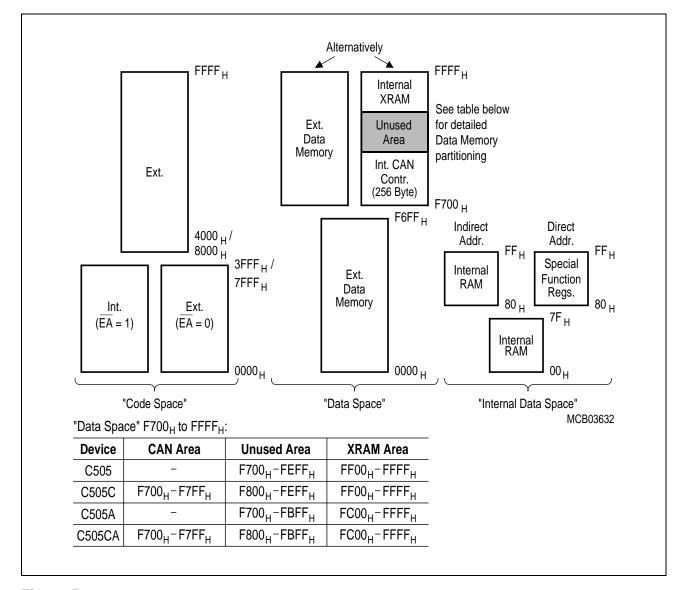


Figure 5 C505 Memory Map Memory Map



Reset and System Clock

The reset input is an active high input at pin RESET. Since the reset is synchronized internally, the RESET pin must be held high for at least two machine cycles (12 oscillator periods) while the oscillator is running. A pulldown resistor is internally connected to $V_{\rm SS}$ to allow a power-up reset with an external capacitor only. An automatic reset can be obtained when $V_{\rm DD}$ is applied by connecting the RESET pin to $V_{\rm DD}$ via a capacitor. Figure 6 shows the possible reset circuitries.

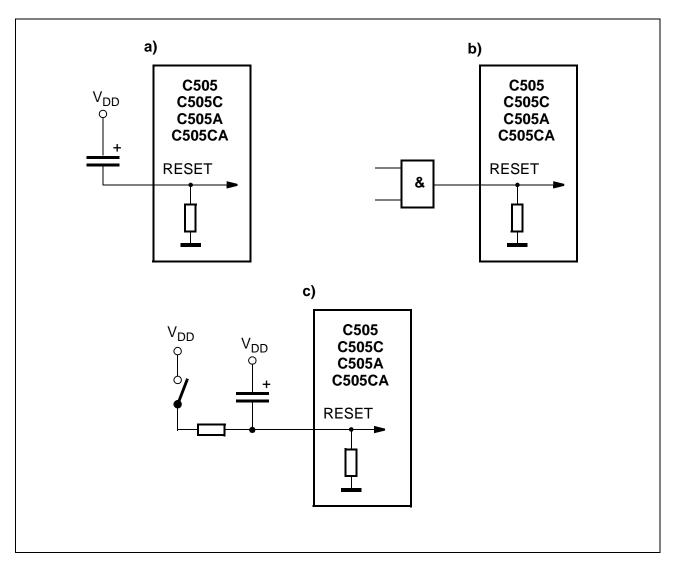


Figure 6
Reset Circuitries

Data Sheet 14 12.00



Figure 7 shows the recommended oscillator circuits for crystal and external clock operation.

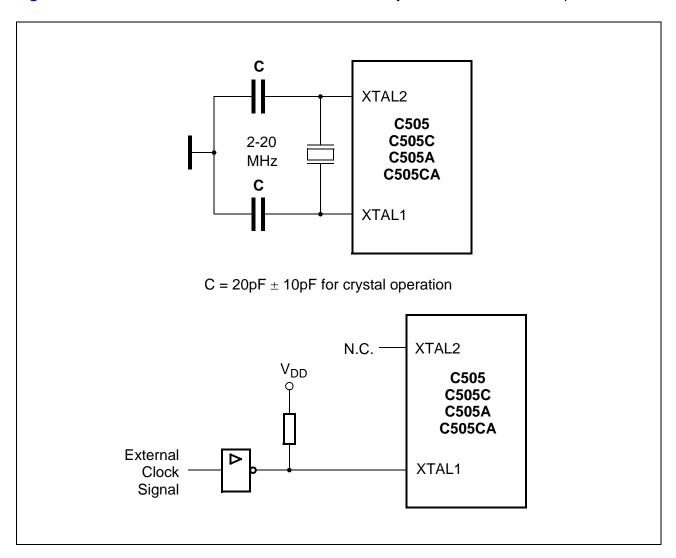


Figure 7
Recommended Oscillator Circuitries

Data Sheet 15 12.00



Multiple Datapointers

As a functional enhancement to the standard 8051 architecture, the C505 contains eight 16-bit datapointers instead of only one datapointer. The instruction set uses just one of these datapointers at a time. The selection of the actual datapointer is done in the special function regsiter DPSEL. **Figure 8** illustrates the datapointer addressing mechanism.

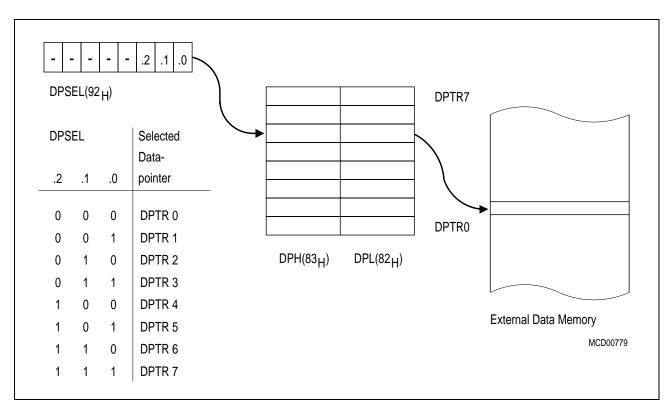


Figure 8
External Data Memory Addressing using Multiple Datapointers

Data Sheet 16 12.00



Enhanced Hooks Emulation Concept

The Enhanced Hooks Emulation Concept of the C500 microcontroller family is a new, innovative way to control the execution of C500 MCUs and to gain extensive information on the internal operation of the controllers. Emulation of on-chip ROM based programs is possible, too.

Each production chip has built-in logic for the supprt of the Enhanced Hooks Emulation Concept. Therefore, no costly bond-out chips are necessary for emulation. This also ensure that emulation and production chips are identical.

The Enhanced Hooks Technology^{TM 1)}, which requires embedded logic in the C500 allows the C500 together with an EH-IC to function similar to a bond-out chip. This simplifies the design and reduces costs of an ICE-system. ICE-systems using an EH-IC and a compatible C500 are able to emulate all operating modes of the different versions of the C500 microcontrollers. This includes emulation of ROM, ROM with code rollover and ROMless modes of operation. It is also able to operate in single step mode and to read the SFRs after a break.

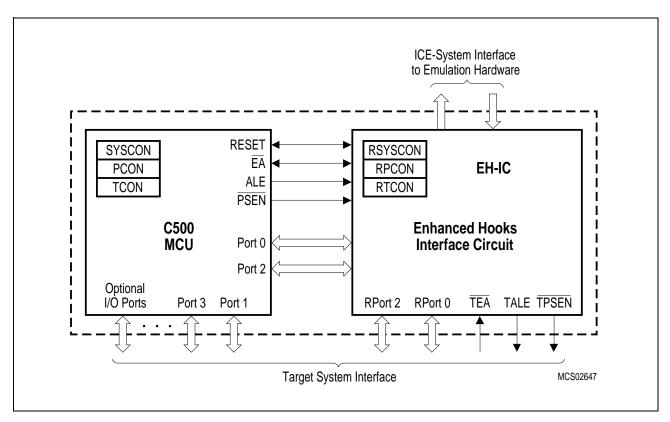


Figure 9
Basic C500 MCU Enhanced Hooks Concept Configuration

Port 0, port 2 and some of the control lines of the C500 based MCU are used by Enhanced Hooks Emulation Concept to control the operation of the device during emulation and to transfer informations about the programm execution and data transfer between the external emulation hardware (ICE-system) and the C500 MCU.

Data Sheet 17 12.00

^{1) &}quot;Enhanced Hooks Technology" is a trademark and patent of Metalink Corporation licensed to Infineon Technologies.

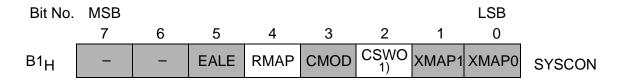


Special Function Registers

The registers, except the program counter and the four general purpose register banks, reside in the special function register area. The special function register area consists of two portions: the standard special function register area and the mapped special function register area. Five special function register of the C505 (PCON1,P1ANA, VR0, VR1, VR2) are located in the mapped special function register area. For accessing the mapped special function register area, bit RMAP in special function register SYSCON must be set. All other special function registers are located in the standard special function register area which is accessed when RMAP is cleared ("0").

The registers and data locations of the CAN controller (CAN-SFRs) are located in the external data memory area at addresses F700_H to F7FF_H..





The functions of the shaded bits are not described here.

1) This bit is only available in the C505CA.

Bit	Function
RMAP	Special function register map bit RMAP = 0: The access to the non-mapped (standard) special function register area is enabled. RMAP = 1: The access to the mapped special function register area is enabled.
CSWO	CAN Controller switch-off bit CSWO = 0 : CAN Controller is enabled (default after reset). CSWO = 1 : CAN Controller is switched off.

As long as bit RMAP is set, mapped special function register area can be accessed. This bit is not cleared by hardware automatically. Thus, when non-mapped/mapped registers are to be accessed, the bit RMAP must be cleared/set respectively by software.

All SFRs with addresses where address bits 0-2 are 0 (e.g. 80_H, 88_H, 90_H, 98_H, ..., F8_H, FF_H) are bitaddressable.

The 52 special function registers (SFRs) in the standard and mapped SFR area include pointers and registers that provide an interface between the CPU and the other on-chip peripherals. The SFRs of the C505 are listed in **Table 3** and **Table 4**. In **Table 3** they are organized in groups which refer to the functional blocks of the C505. The CAN-SFRs (applicable for the C505C and C505CA only) are also included in **Table 3**. **Table 4** illustrates the contents of the SFRs in numeric order of their addresses. **Table 5** list the CAN-SFRs in numeric order of their addresses.

Data Sheet 18 12.00



Table 3 Special Function Registers - Functional Blocks

Block	Symbol	Name	Address	Contents after Reset
CPU	ACC	Accumulator	E0 _H 1)	00 _H
	В	B-Register	F0H ¹⁾	00H
	DPH	Data Pointer, High Byte	83 _H	00H
	DPL	Data Pointer, Low Byte	82 _H	00H
	DPSEL	Data Pointer Select Register	92 _H	XXXXX000 _B 3)
	PSW	Program Status Word Register	D0H 1)	00 _H
	SP	Stack Pointer	81 _H	07 _H
	SYSCON ²⁾	System Control Register	B1 _H	XX100X01 _B ^{3) 6)} XX100001 _B ^{3) 7)}
	VR0 4)	Version Register 0	FC _H	C5 _H
	VR1 ⁴⁾	Version Register 1	FD _H	05 _H
	VR2 4)	Version Register 2	FEH	5)
A/D-	ADCON0 ²⁾	A/D Converter Control Register 0	D8 _H 1)	00X00000 _B ³⁾
Converter	ADCON1	A/D Converter Control Register 1	DCH	01XXX000 _B ³⁾
	ADDAT	A/D Converter Data Reg. (C505/C505C)	D9H	00 _H
	ADST	A/D Converter Start Reg. (C505/C505C)	DAH	XXH 3)
	ADDATH	A/D Converter High Byte Data Register (C505A/C505CA)	D9H	00H
	ADDATL	A/D Converter Low Byte Data Register (C505A/C505CA)	DA _H	00XXXXXX _B ³⁾
	P1ANA 2) 4)	Port 1 Analog Input Selection Register	90 _H	FF _H
Interrupt	IEN0 ²⁾	Interrupt Enable Register 0	A8H 1)	00 _H
System	IEN1 2)	Interrupt Enable Register 1	B8H 1)	00 _H
	IP0 ²⁾	Interrupt Priority Register 0	A9 _H	00 _H
	IP1	Interrupt Priority Register 1	B9 _H	XX000000 _B ³⁾
	TCON 2)	Timer Control Register	88H 1)	00 _H
	T2CON 2)	Timer 2 Control Register	C8H 1)	00X00000 _B
	SCON 2)	Serial Channel Control Register	98H 1)	00 _H
	IRCON	Interrupt Request Control Register	C0H 1)	00 _H
XRAM	XPAGE	Page Address Register for Extended on-chip XRAM and CAN Controller	91 _H	00 _H
	SYSCON ²⁾	System Control Register	B1 _H	XX100X01 _B ^{3) 6)} XX100001 _B ^{3) 7)}

¹⁾ Bit-addressable special function registers

Data Sheet 19 12.00

²⁾ This special function register is listed repeatedly since some bits of it also belong to other functional blocks.

^{3) &}quot;X" means that the value is undefined and the location is reserved

⁴⁾ This SFR is a mapped SFR. For accessing this SFR, bit RMAP in SFR SYSCON must be set.

⁵⁾ The content of this SFR varies with the actual step of the C505 (eg. 01_H for the first step)

⁶⁾ C505 / C505A/C505C only

⁷⁾ C505CA only



Table 3
Special Function Registers - Functional Blocks (cont'd)

Block	Symbol	Name	Address	Contents after Reset
Ports	P0	Port 0	80 _H 1)	FFH
	P1	Port 1	90H 1)	FFH
	P1ANA 2) 4)	Port 1 Analog Input Selection Register	90H 1)	FFH
	P2	Port 2	A0 _H 1)	FFH
	P3	Port 3	B0H 1)	FFH
	P4	Port 4	E8H 1)	XXXXXX11 _B
Serial	ADCON0 ²⁾	A/D Converter Control Register 0	D8 _H 1)	00X00000 _B ³⁾
Channel	PCON ²⁾	Power Control Register	87 _H	00 _H
	SBUF	Serial Channel Buffer Register	99H	XXH 3)
	SCON	Serial Channel Control Register	98H 1)	00H
	SRELL	Serial Channel Reload Register, low byte	AAH	D9H
	SRELH	Serial Channel Reload Register, high byte	BAH	XXXXXX11 _B ³⁾
Timer 0/	TCON	Timer 0/1 Control Register	88 _H ¹)	00 _H
Timer 1	TH0	Timer 0, High Byte	8C _H	00H
	TH1	Timer 1, High Byte	8DH	00H
	TL0	Timer 0, Low Byte	8A _H	00H
	TL1	Timer 1, Low Byte	8B _H	00H
	TMOD	Timer Mode Register	89H	00H
Compare/	CCEN	Comp./Capture Enable Reg.	C1 _H	00H 3)
Capture	CCH1	Comp./Capture Reg. 1, High Byte	C3H	00H
Unit /	CCH2	Comp./Capture Reg. 2, High Byte	C5 _H	00H
Timer 2	CCH3	Comp./Capture Reg. 3, High Byte	C7H	00H
	CCL1	Comp./Capture Reg. 1, Low Byte	C2H	00H
	CCL2	Comp./Capture Reg. 2, Low Byte	C4 _H	00H
	CCL3	Comp./Capture Reg. 3, Low Byte	C6H	00H
	CRCH	Reload Register High Byte	CB _H	00H
	CRCL	Reload Register Low Byte	CAH	00H
	TH2	Timer 2, High Byte	CDH	00H
	TL2	Timer 2, Low Byte	CCH	00H
	T2CON	Timer 2 Control Register	C8H ¹⁾	00X00000 _B ³⁾
	IEN0 ²⁾	Interrupt Enable Register 0	A8 _H 1)	00H
	IEN1 2)	Interrupt Enable Register 1	B8H 1)	00H
Watchdog	WDTREL	Watchdog Timer Reload Register	86 _H	00 _H
· ·	IEN0 ²⁾	Interrupt Enable Register 0	A8H 1)	00H
	IEN1 2)	Interrupt Enable Register 1	B8H 1)	00H
	IP0 ²⁾	Interrupt Priority Register 0	A9 _H	00H
Pow. Save	PCON ²⁾	Power Control Register	87 _H	00 _H
Modes	PCON1 4)	Power Control Register 1	88H 1)	0XX0XXXX _B 3)

¹⁾ Bit-addressable special function registers

Data Sheet 20 12.00

²⁾ This special function register is listed repeatedly since some bits of it also belong to other functional blocks.

^{3) &}quot;X" means that the value is undefined and the location is reserved

⁴⁾ SFR is located in the mapped SFR area. For accessing this SFR, bit RMAP in SFR SYSCON must be set.



Table 3
Special Function Registers - Functional Blocks (cont'd)

Block	Symbol	Name	Address	Contents after Reset
CAN	CR	Control Register	F700 _H	01 _H
Controller	SR	Status Register	F701 _H	XXH 3)
	IR	Interrupt Register	F702 _H	XXH ³⁾
(C505C/	BTR0	Bit Timing Register Low	F704 _H	UUH 3)
C505CA	BTR1	Bit Timing Register High	F705H	0UUUUUU _B 3)
only)	GMS0	Global Mask Short Register Low	F706H	UU _H 3)
	GMS1	Global Mask Short Register High	F707H	UUU11111 _B 3)
	UGML0	Upper Global Mask Long Register Low	F708H	UU _H 3)
	UGML1	Upper Global Mask Long Register High	F709H	UUH 3)
	LGML0	Lower Global Mask Long Register Low	F70A _H	UU _H 3)
	LGML1	Lower Global Mask Long Register High	F70BH	UUUUU000 _B 3)
	UMLM0	Upper Mask of Last Message Register Low	F70C _H	UU _H 3)
	UMLM1	Upper Mask of Last Message Register High	F70D _H	UU _H 3)
	LMLMO	Lower Mask of Last Message Register Low	F70E _H	UU _H 3)
	LMLM1	Lower Mask of Last Message Register High	F70F _H	UUUUU000 _B 3)
		Message Object Registers :		
	MCR0	Message Control Register Low	F7n0 _H 5)	UU _H 3)
	MCR1	Message Control Register High	F7n1 _H 5)	UUH ³⁾
	UAR0	Upper Arbitration Register Low	F7n2 _H 5)	UU _H 3)
	UAR1	Upper Arbitration Register High	F7n3 _H 5)	UU _H 3)
	LAR0	Lower Arbitration Register Low	F7n4H 5)	UU _H 3)
	LAR1	Lower Arbitration Register High	F7n5 _H 5)	UUUUU000 _B 3)
	MCFG	Message Configuration Register	F7n6 _H 5)	UUUUUU00 _B 3)
	DB0	Message Data Byte 0	F7n7 _H 5)	XXH ³⁾
	DB1	Message Data Byte 1	F7n8 _H 5)	XXH ³⁾
	DB2	Message Data Byte 2	F7n9 _H 5)	XXH ³⁾
	DB3	Message Data Byte 3	F7nA _H 5)	XXH ³⁾
	DB4	Message Data Byte 4	F7nB _H ⁵⁾	XXH 3)
	DB5	Message Data Byte 5	F7nC _H 5)	XXH 3)
	DB6	Message Data Byte 6	F7nD _H 5)	XXH 3)
	DB7	Message Data Byte 7	F7nE _H 5)	XXH ³⁾

¹⁾ Bit-addressable special function registers

Data Sheet 21 12.00

²⁾ This special function register is listed repeatedly since some bits of it also belong to other functional blocks.

^{3) &}quot;X" means that the value is undefined and the location is reserved. "U" means that the value is unchanged by a reset operation. "U" values are undefined (as "X") after a power-on reset operation

⁴⁾ SFR is located in the mapped SFR area. For accessing this SFR, bit RMAP in SFR SYSCON must be set.

⁵⁾ The notation "n" (n= 1 to F) in the message object address definition defines the number of the related message object.



Table 4
Contents of the SFRs, SFRs in numeric order of their addresses

Addr	Register	Content after Reset ¹⁾	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
80H ²⁾	P0	FFH	.7	.6	.5	.4	.3	.2	.1	.0
81 _H	SP	07 _H	.7	.6	.5	.4	.3	.2	.1	.0
82 _H	DPL	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
83 _H	DPH	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
86 _H	WDTREL	00 _H	WDT PSEL	.6	.5	.4	.3	.2	.1	.0
87 _H	PCON	00 _H	SMOD	PDS	IDLS	SD	GF1	GF0	PDE	IDLE
88H ²⁾	TCON	00H	TF1	TR1	TF0	TR0	IE1	IT1	IE0	IT0
88H³)	PCON1	0XX0- XXXX _B	EWPD	-	-	WS	-	-	-	_
89 _H	TMOD	00 _H	GATE	C/T	M1	МО	GATE	C/T	M1	МО
8A _H	TL0	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
8B _H	TL1	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
8C _H	TH0	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
8D _H	TH1	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
90H ²⁾	P1	FFH	T2	CLK- OUT	T2EX	.4	INT6	INT5	INT4	.INT3
90H ³⁾	P1ANA	FFH	EAN7	EAN6	EAN5	EAN4	EAN3	EAN2	EAN1	EAN0
91 _H	XPAGE	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
92 _H	DPSEL	XXXX- X000B	_	_	_	_	_	.2	.1	.0
98H ²⁾	SCON	00 _H	SM0	SM1	SM2	REN	TB8	RB8	TI	RI
99 _H	SBUF	хх _Н	.7	.6	.5	.4	.3	.2	.1	.0
A0H ²⁾	P2	FFH	.7	.6	.5	.4	.3	.2	.1	.0
A8 _H ²⁾	IEN0	00 _H	EA	WDT	ET2	ES	ET1	EX1	ET0	EX0
A9 _H	IP0	00 _H	OWDS	WDTS	.5	.4	.3	.2	.1	.0
AAH	SRELL	D9 _H	.7	.6	.5	.4	.3	.2	.1	.0

¹⁾ X means that the value is undefined and the location is reserved $\,$

Data Sheet 22 12.00

²⁾ Bit-addressable special function registers

³⁾ SFR is located in the mapped SFR area. For accessing this SFR, bit RMAP in SFR SYSCON must be set.



Table 4
Contents of the SFRs, SFRs in numeric order of their addresses (cont'd)

Addr	Register	Content after Reset ¹⁾	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
B0H ²⁾	P3	FFH	RD	WR	T1	ТО	ĪNT1	ĪNT0	TxD	RxD
B1 _H	SYSCON 3)	XX10- 0X01 _B	_	_	EALE	RMAP	CMOD	_	XMAP1	XMAP0
B1 _H	SYSCON 4)	XX10- 0001 _B	_	_	EALE	RMAP	CMOD	CSWO	XMAP1	XMAP0
B8 _H ²⁾	IEN1	00 _H	EXEN2	SWDT	EX6	EX5	EX4	EX3	ECAN	EADC
B9 _H	IP1	XX00- 0000 _B	_	_	.5	.4	.3	.2	.1	.0
BA _H	SRELH	XXXX- XX11 _B	_	_	_	-	_	_	.1	.0
C0H ²⁾	IRCON	00 _H	EXF2	TF2	IEX6	IEX5	IEX4	IEX3	SWI	IADC
C1 _H	CCEN	00 _H	COCA H3	COCAL 3	COCA H2	COCAL 2	COCA H1	COCAL 1	COCA H0	COCAL 0
C2 _H	CCL1	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
C3 _H	CCH1	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
C4 _H	CCL2	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
C5 _H	CCH2	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
C6 _H	CCL3	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
C7 _H	ССН3	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
C8 _H ²⁾	T2CON	00X0- 0000B	T2PS	I3FR	-	T2R1	T2R0	T2CM	T2I1	T2I0
CAH	CRCL	00H	.7	.6	.5	.4	.3	.2	.1	.0
СВН	CRCH	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
CCH	TL2	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
CDH	TH2	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
D0H ²⁾	PSW	00 _H	CY	AC	F0	RS1	RS0	OV	F1	Р
D8 _H ²⁾	ADCON0	00X0- 0000 _B	BD	CLK	_	BSY	ADM	MX2	MX1	MX0

¹⁾ X means that the value is undefined and the location is reserved

Data Sheet 23 12.00

²⁾ Bit-addressable special function registers

³⁾ C505 /C505C/C505A only

⁴⁾ C505CA only



Table 4
Contents of the SFRs, SFRs in numeric order of their addresses (cont'd)

Addr	Register	Content after Reset ¹⁾	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
D9 _H	ADDAT 6)	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
D9 _H	ADDATH	00H	.9	.8	.7	.6	.5	.4	.3	.2
DA _H	ADST 6)	XXXX- XXXX _B	_	_	_	_	_	_	_	_
DA _H	ADDATL	00XX- XXXX _B	.1	.0	_	_	_	_	_	_
DCH	ADCON1	01XX- X000 _B	ADCL1	ADCL0	_	_	_	MX2	MX1	MX0
E0 _{H²⁾}	ACC	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
E8H ²⁾	P4	XXXX- XX11 _B	_	_	_	-	_	_	RXDC	TXDC
F0 _{H²⁾}	В	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
FCH ³⁾⁴⁾	VR0	C5 _H	1	1	0	0	0	1	0	1
FDH ³⁾⁴⁾	VR1	05 _H	0	0	0	0	0	1	0	1
FEH ³⁾⁴⁾	VR2 ⁵⁾	01H ₉) 12H ₉) 33H ₁₀)	.7	.6	.5	.4	.3	.2	.1	.0

- 1) X means that the value is undefined and the location is reserved
- 2) Bit-addressable special function registers
- 3) SFR is located in the mapped SFR area. For accessing this SFR, bit RMAP in SFR SYSCON must be set.
- 4) These are read-only registers
- 5) The content of this SFR varies with the actual of the step C505 (eg. 01_H or 11_H or 21_H for the first step)
- 6) C505 / C505C only
- 7) C505A / C505CA only
- 8) C505 / C505C AB step only
- 9) C505A-4E / C505CA-4E BA step only (11_H for the AA step)
- 10) C505A-4R / C505CA-4R BB step only (32_H for the BA step)

Data Sheet 24 12.00



Table 5
Contents of the CAN Registers in numeric order of their addresses (C505C/C505CA only)

Addr. n=1-F _H	Register	Content after Reset ²⁾	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	
F700 _H	CR	01 _H	TEST	CCE	0	0	EIE	SIE	IE	INIT	
F701 _H	SR	хх _Н	BOFF	EWRN	_	RXOK	TXOK	LEC2	LEC1	LEC0	
F702 _H	IR	хх _Н				IN ⁻	TID				
F704 _H	BTR0	UU _H	S	JW			ВІ	RP			
F705 _H	BTR1	0UUU. UUUU _B	0		TSEG2			TS	EG1		
F706 _H	GMS0	UU _H				ID2	8-21				
F707 _H	GMS1	UUU1. 1111 _B		ID20-18 1			1	1	1	1	
F708 _H	UGML0	UU _H		ID28-21							
F709 _H	UGML1	UU _H		ID20-13							
F70A _H	LGML0	UU _H				ID1	2-5				
F70B _H	LGML1	UUUU. U000 _B			ID4-0			0	0	0	
F70C _H	UMLM0	UU _H				ID2	8-21				
F70D _H	UMLM1	UU _H		ID20-18				ID17-13	13		
F70E _H	LMLM0	UU _H				ID1	2-5				
F70F _H	LMLM1	UUUU. U000 _B			ID4-0			0	0	0	
F7n0 _H	MCR0	UU _H	MSG	SVAL	T	(IE	R)	KIE	INT	PND	
F7n1 _H	MCR1	UU _H	RMTPND TXRQ					MSGLST NEWDAT CPUUPD			
F7n2 _H	UAR0	UU _H	ID28-21								
F7n3 _H	UAR1	UU _H	ID20-18 ID17-13								
F7n4 _H	LAR0	UU _H				ID1	2-5				
F7n5 _H	LAR1	UUUU. U000 _B			ID4-0			0	0	0	

¹⁾ The notation "n" (n= 1 to F) in the address definition defines the number of the related message object.

Data Sheet 25 12.00

^{2) &}quot;X" means that the value is undefined and the location is reserved. "U" means that the value is unchanged by a reset operation. "U" values are undefined (as "X") after a power-on reset operation



Table 5
Contents of the CAN Registers in numeric order of their addresses (cont'd) (C505C/C505CA only)

Addr. n=1-F _H	Register	Content after Reset ²⁾	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
F7n6 _H	MCFG	UUUU. UU00 _B		DI	_C		DIR	XTD	0	0
F7n7 _H	DB0	ХХН	.7	.6	.5	.4	.3	.2	.1	.0
F7n8 _H	DB1	хх _Н	.7	.6	.5	.4	.3	.2	.1	.0
F7n9 _H	DB2	хх _Н	.7	.6	.5	.4	.3	.2	.1	.0
F7nA _H	DB3	хх _Н	.7	.6	.5	.4	.3	.2	.1	.0
F7nB _H	DB4	хх _Н	.7	.6	.5	.4	.3	.2	.1	.0
F7nC _H	DB5	хх _Н	.7	.6	.5	.4	.3	.2	.1	.0
F7nD _H	DB6	хх _Н	.7	.6	.5	.4	.3	.2	.1	.0
F7nE _H	DB7	хх _Н	.7	.6	.5	.4	.3	.2	.1	.0

¹⁾ The notation "n" (n= 1 to F) in the address definition defines the number of the related message object.

Data Sheet 26 12.00

^{2) &}quot;X" means that the value is undefined and the location is reserved. "U" means that the value is unchanged by a reset operation. "U" values are undefined (as "X") after a power-on reset operation



I/O Ports

The C505 has four 8-bit I/O ports and one 2-bit I/O port. Port 0 is an open-drain bidirectional I/O port, while ports 1 to 4 are quasi-bidirectional I/O ports with internal pullup resistors. That means, when configured as inputs, ports 1 to 4 will be pulled high and will source current when externally pulled low. Port 0 will float when configured as input.

The output drivers of port 0 and 2 and the input buffers of port 0 are also used for accessing external memory. In this application, port 0 outputs the low byte of the external memory address, time multiplexed with the byte being written or read. Port 2 outputs the high byte of the external memory address when the address is 16 bits wide. Otherwise, the port 2 pins continue emitting the P2 SFR contents. In this function, port 0 is not an open-drain port, but uses a strong internal pullup FET.

Port 4 is 2-bit I/O port with CAN controller specific alternate functions. The eight analog input lines are realized as mixed digital/analog inputs. The 8 analog inputs, AN0-AN7, are located at the port 1 pins P1.0 to P1.7. After reset, all analog inputs are disabled and the related pins of port 1 are configured as digital inputs. The analog function of a specific port 1 pin is enabled by bits in the SFR P1ANA. Writing a 0 to a bit position of P1ANA assigns the corresponding pin to operate as analog input.

Note: P1ANA is a mapped SFR and can be only accessed if bit RMAP in SFR SYSCON is set.

Data Sheet 27 12.00



Timer / Counter 0 and 1

Timer/Counter 0 and 1 can be used in four operating modes as listed in Table 6:

Table 6
Timer/Counter 0 and 1 Operating Modes

Mode	Description	TMOD		Input Clock			
		M1	МО	internal	external (max)		
0	8-bit timer/counter with a divide-by-32 prescaler	0	0	f _{OSC} /6x32	f _{osc} /12x32		
1	16-bit timer/counter	0	1				
2	8-bit timer/counter with 8-bit autoreload	1	0	£ /6	£ /42		
3	Timer/counter 0 used as one 8-bit timer/counter and one 8-bit timer Timer 1 stops	1	1	$f_{ m osc}$ /6	$f_{ m osc}$ /12		

In the "timer" function (C/\overline{T} = '0') the register is incremented every machine cycle. Therefore the count rate is $f_{OSC}/6$.

In the "counter" function the register is incremented in response to a 1-to-0 transition at its corresponding external input pin (P3.4/T0, P3.5/T1). Since it takes two machine cycles to detect a falling edge the max. count rate is $f_{\rm OSC}/12$. External inputs $\overline{\rm INT0}$ and $\overline{\rm INT1}$ (P3.2, P3.3) can be programmed to function as a gate to facilitate pulse width measurements. **Figure 10** illustrates the input clock logic.

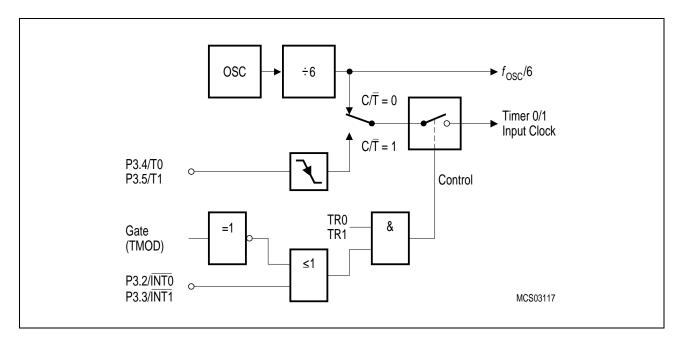


Figure 10
Timer/Counter 0 and 1 Input Clock Logic

Data Sheet 28 12.00



Timer/Counter 2 with Compare/Capture/Reload

The timer 2 of the C505 provides additional compare/capture/reload features. which allow the selection of the following operating modes:

Compare : up to 4 PWM signals with 16-bit/300 ns resolution (@ 20 MHz clock)

Capture : up to 4 high speed capture inputs with 300 ns resolution

Reload : modulation of timer 2 cycle time

The block diagram in **Figure 11** shows the general configuration of timer 2 with the additional compare/capture/reload registers. The I/O pins which can used for timer 2 control are located as multifunctional port functions at port 1.

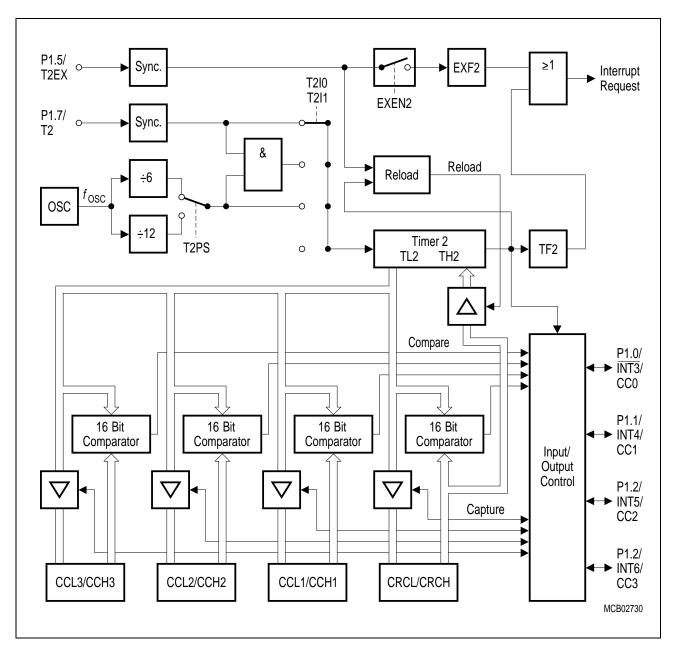


Figure 11 Timer 2 Block Diagram

Data Sheet 29 12.00



Timer 2 Operating Modes

The timer 2, which is a 16-bit-wide register, can operate as timer, event counter, or gated timer. A roll-over of the count value in TL2/TH2 from all 1's to all 0's sets the timer overflow flag TF2 in SFR IRCON, which can generate an interrupt. The bits in register T2CON are used to control the timer 2 operation.

<u>Timer Mode</u>: In timer function, the count rate is derived from the oscillator frequency. A prescaler offers the possibility of selecting a count rate of 1/6 or 1/12 of the oscillator frequency.

<u>Gated Timer Mode</u>: In gated timer function, the external input pin T2 (P1.7) functions as a gate to the input of timer 2. If T2 is high, the internal clock input is gated to the timer. T2 = 0 stops the counting procedure. This facilitates pulse width measurements. The external gate signal is sampled once every machine cycle.

<u>Event Counter Mode</u>: In the event counter function, the timer 2 is incremented in response to a 1-to-0 transition at its corresponding external input pin T2 (P1.7). In this function, the external input is sampled every machine cycle. Since it takes two machine cycles (12 oscillator periods) to recognize a 1-to-0 transition, the maximum count rate is 1/6 of the oscillator frequency. There are no restrictions on the duty cycle of the external input signal, but to ensure that a given level is sampled at least once before it changes, it must be held for at least one full machine cycle.

Reload of Timer 2: Two reload modes are selectable:

In mode 0, when timer 2 rolls over from all 1's to all 0's, it not only sets TF2 but also causes the timer 2 registers to be loaded with the 16-bit value in the CRC register, which is preset by software. In mode 1, a 16-bit reload from the CRC register is caused by a negative transition at the corresponding input pin P1.5/T2EX. This transition will also set flag EXF2 if bit EXEN2 in SFR IEN1 has been set.

Data Sheet 30 12.00



Timer 2 Compare Modes

The compare function of a timer/register combination operates as follows: the 16-bit value stored in a compare or compare/capture register is compared with the contents of the timer register; if the count value in the timer register matches the stored value, an appropriate output signal is generated at a corresponding port pin and an interrupt can be generated.

Compare Mode 0

In compare mode 0, upon matching the timer and compare register contents, the output signal changes from low to high. It goes back to a low level on timer overflow. As long as compare mode 0 is enabled, the appropriate output pin is controlled by the timer circuit only and writing to the port will have no effect. Figure 12 shows a functional diagram of a port circuit when used in compare mode 0. The port latch is directly controlled by the timer overflow and compare match signals. The input line from the internal bus and the write-to-latch line of the port latch are disconnected when compare mode 0 is enabled.

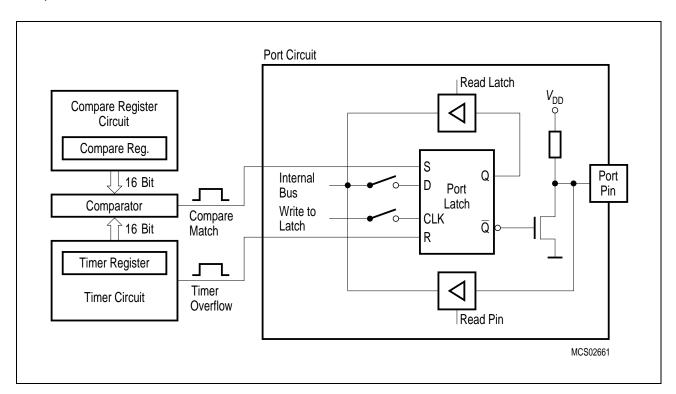


Figure 12
Port Latch in Compare Mode 0

Data Sheet 31 12.00



Compare Mode 1

If compare mode 1 is enabled and the software writes to the appropriate output latch at the port, the new value will not appear at the output pin until the next compare match occurs. Thus, it can be choosen whether the output signal has to make a new transition (1-to-0 or 0-to-1, depending on the actual pin-level) or should keep its old value at the time when the timer value matches the stored compare value.

In compare mode 1 (see **Figure 13**) the port circuit consists of two separate latches. One latch (which acts as a "shadow latch") can be written under software control, but its value will only be transferred to the port latch (and thus to the port pin) when a compare match occurs.

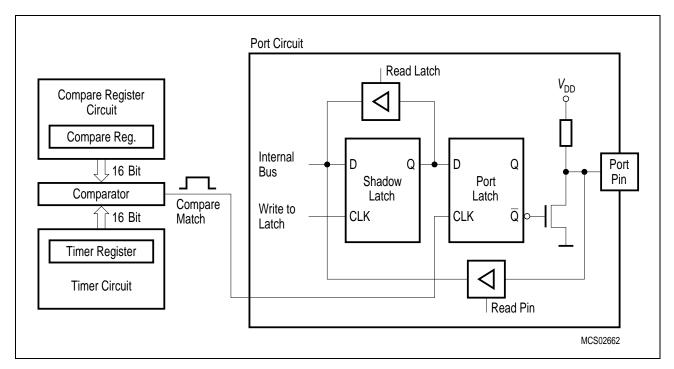


Figure 13
Compare Function in Compare Mode 1

Timer 2 Capture Modes

Each of the compare/capture registers CC1 to CC3 and the CRC register can be used to latch the current 16-bit value of the timer 2 registers TL2 and TH2. Two different modes are provided for this function.

In mode 0, the external event causing a capture is:

- for CC registers 1 to 3: a positive transition at pins CC1 to CC3 of port 1
- for the CRC register: a positive or negative transition at the corresponding pin, depending on the status of the bit I3FR in SFR T2CON.

In <u>mode 1</u> a capture occurs in response to a write instruction to the low order byte of a capture register. The write-to-register signal (e.g. write-to-CRCL) is used to initiate a capture. The timer 2 contents will be latched into the appropriate capture register in the cycle following the write instruction. In this mode no interrupt request will be generated.

Data Sheet 32 12.00



Serial Interface (USART)

The serial port is full duplex and can operate in four modes (one synchronous mode, three asynchronous modes) as illustrated in **Table 7**.

Table 7
USART Operating Modes

Mada	SCON		Description
Mode	SM0	SM1	
0	0	0	Shift register mode, fixed baud rate Serial data enters and exits through R×D; T×D outputs the shift clock; 8-bit are transmitted/received (LSB first)
1	0	1	8-bit UART, variable baud rate 10 bits are transmitted (through T×D) or received (at R×D)
2	1	0	9-bit UART, fixed baud rate 11 bits are transmitted (through T×D) or received (at R×D)
3	1	1	9-bit UART, variable baud rate Like mode 2

For clarification some terms regarding the difference between "baud rate clock" and "baud rate" should be mentioned. In the <u>asynchronous modes</u> the serial interfaces require a clock rate which is 16 times the baud rate for internal synchronization. Therefore, the baud rate generators/timers have to provide a "baud rate clock" (output signal in **Figure 14** to the serial interface which - there divided by 16 - results in the actual "baud rate". Further, the abbrevation f_{OSC} refers to the oscillator frequency (crystal or external clock operation).

The variable baud rates for modes 1 and 3 of the serial interface can be derived either from timer 1 or from a decdicated baud rate generator (see **Figure 14**).

Data Sheet 33 12.00



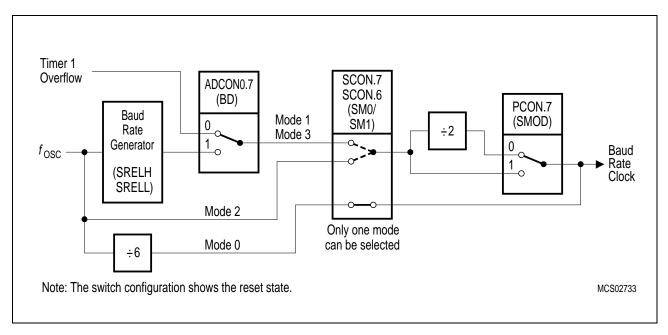


Figure 14
Block Diagram of Baud Rate Generation for the Serial Interface

Table 8 below lists the values/formulas for the baud rate calculation of the serial interface with its dependencies of the control bits BD and SMOD.

Table 8
Serial Interface - Baud Rate Dependencies

Serial Interface	Active Control Bits		Baud Rate Calculation
Operating Modes	BD SMOD		
Mode 0 (Shift Register)	_	_	$f_{ m OSC}$ / 6
Mode 1 (8-bit UART) Mode 3 (9-bit UART)	0	X	Controlled by timer 1 overflow : (2 ^{SMOD} × timer 1 overflow rate) / 32
	1	Х	Controlled by baud rate generator $(2^{\text{SMOD}} \times f_{\text{OSC}})$ / $(32 \times \text{baud rate generator overflow rate})$
Mode 2 (9-bit UART)	_	0	f _{osc} / 32 f _{osc} / 16

Data Sheet 34 12.00



CAN Controller (C505C and C505CA only)

The on-chip CAN controller, compliant to version 2.0B, is the functional heart which provides all resources that are required to run the standard CAN protocol (11-bit identifiers) as well as the extended CAN protocol (29-bit identifiers). It provides a sophisticated object layer to relieve the CPU of as much overhead as possible when controlling many different message objects (up to 15). This includes bus arbitration, resending of garbled messages, error handling, interrupt generation, etc. In order to implement the physical layer, external components have to be connected to the C505C/C505CA.

The internal bus interface connects the on-chip CAN controller to the internal bus of the microcontroller. The registers and data locations of the CAN interface are mapped to a specific 256 byte wide address range of the external data memory area (F700_H to F7FF_H) and can be accessed using MOVX instructions. **Figure 15** shows a block diagram of the on-chip CAN controller.

The **TX/RX Shift Register** holds the destuffed bit stream from the bus line to allow the parallel access to the whole data or remote frame for the acceptance match test and the parallel transfer of the frame to and from the Intelligent Memory.

The **Bit Stream Processor (BSP)** is a sequencer controlling the sequential data stream between the TX/RX Shift Register, the CRC Register, and the bus line. The BSP also controls the EML and the parallel data stream between the TX/RX Shift Register and the Intelligent Memory such that the processes of reception, arbitration, transmission, and error signalling are performed according to the CAN protocol. Note that the automatic retransmission of messages which have been corrupted by noise or other external error conditions on the bus line is handled by the BSP.

The **Cyclic Redundancy Check Register (CRC)** generates the Cyclic Redundancy Check code to be transmitted after the data bytes and checks the CRC code of incoming messages. This is done by dividing the data stream by the code generator polynomial.

The **Error Management Logic (EML)** is responsible for the fault confinement of the CAN device. Its counters, the Receive Error Counter and the Transmit Error Counter, are incremented and decremented by commands from the Bit Stream Processor. According to the values of the error counters, the CAN controller is set into the states error *active*, error *passive* and busoff.

The **Bit Timing Logic (BTL)** monitors the busline input RXDC and handles the busline related bit timing according to the CAN protocol. The BTL synchronizes on a *recessive* to *dominant* busline transition at *Start of Frame* (hard synchronization) and on any further *recessive* to *dominant* busline transition, if the CAN controller itself does not transmit a *dominant* bit (resynchronization). The BTL also provides programmable time segments to compensate for the propagation delay time and for phase shifts and to define the position of the Sample Point in the bit time. The programming of the BTL depends on the baudrate and on external physical delay times.

The **Intelligent Memory** (CAM/RAM array) provides storage for up to 15 message objects of maximum 8 data bytes length. Each of these objects has a unique identifier and its own set of control and status bits. After the initial configuration, the Intelligent Memory can handle the reception and transmission of data without further microcontroller actions.

Data Sheet 35 12.00



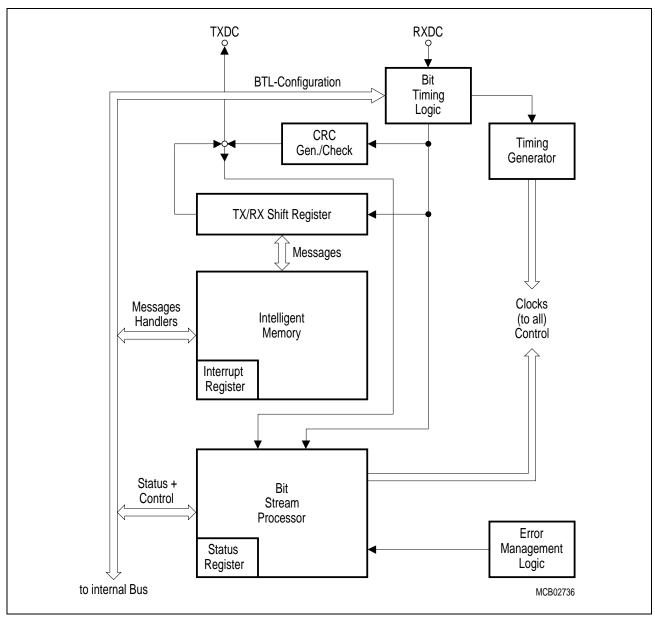


Figure 15
CAN Controller Block Diagram

Data Sheet 36 12.00



CAN Controller Software Initialization

The very first step of the initialization is the CAN controller input clock selection. A divide-by-2 prescaler is enabled by default after reset (**Figure 16**). Setting bit CMOD (SYSCON.3) disables the prescaler. The purpose of the prescaler selection is:

- to ensure that the CAN controller is operable when $f_{\mbox{OSC}}$ is over 10 MHz (bit CMOD =0)
- to achieve the maximum CAN baudrate of 1 Mbaud when f_{OSC} is 8 MHz (bit CMOD=1)

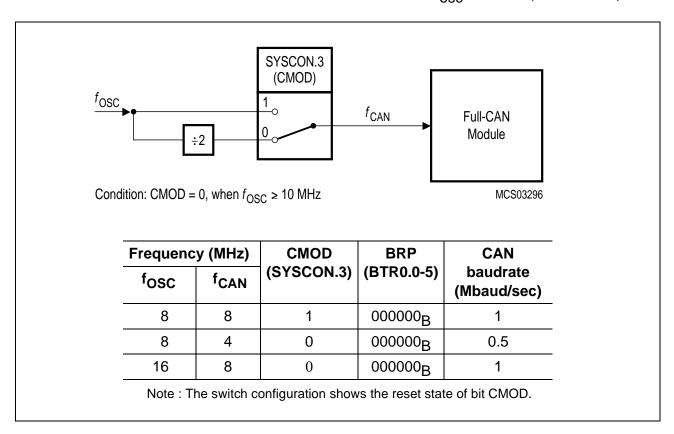


Figure 16
CAN controller Input Clock Selection

Data Sheet 37 12.00

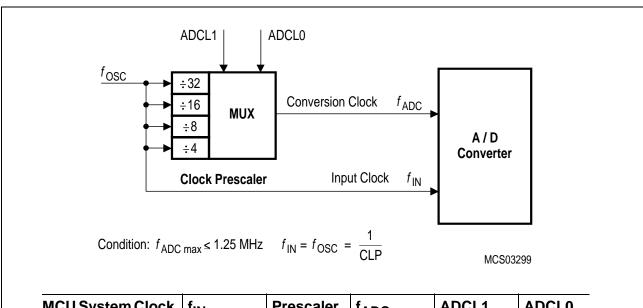


8-Bit A/D Converter (C505 and C505C only)

The C505/C505C includes a high performance / high speed 8-bit A/D converter (ADC) with 8 analog input channels. It operates with a successive approximation technique and provides the following features:

- 8 multiplexed input channels (port 1), which can also be used as digital outputs/inputs
- 8-bit resolution
- Internal start-of-conversion trigger
- Interrupt request generation after each conversion
- Single or continuous conversion mode

The 8-bit ADC uses two clock signals for operation: the conversion clock f_{ADC} (=1/ t_{ADC}) and the input clock f_{IN} (1/ t_{IN}). f_{ADC} is derived from the C505 system clock f_{OSC} which is applied at the XTAL pins via the ADC clock prescaler as shown in **Figure 17**. The input clock is equal to f_{OSC} . The conversion clock f_{ADC} is limited to a maximum frequency of 1.25 MHz. Therefore, the ADC clock prescaler must be programmed to a value which assures that the conversion clock does not exceed 1.25 MHz. The prescaler ratio is selected by the bits ADCL1 and ADCL0 of SFR ADCON1.



MCU System Clock Rate (f _{OSC})	f _{IN} [MHz]	Prescaler Ratio	f _{ADC} [MHz]	ADCL1	ADCL0
2 MHz	2	÷ 4	0.5	0	0
5 MHz	5	÷ 4	1.25	0	0
6 MHz	6	÷ 8	0.75	0	1
10 MHz	10	÷ 8	1.25	0	1
12 MHz	12	÷ 16	0.75	1	0
16 MHz	16	÷ 16	1	1	0
20 MHz	20	÷ 16	1.25	1	0

Figure 17
8-Bit A/D Converter Clock Selection

Data Sheet 38 12.00



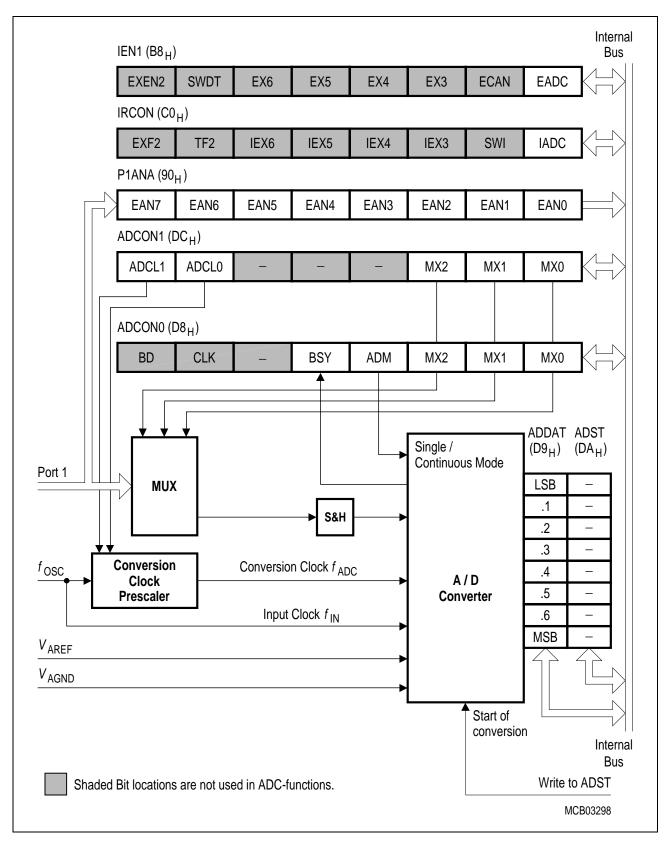


Figure 18
Block Diagram of the 8-Bit A/D Converter

Data Sheet 39 12.00



10-Bit A/D Converter (C505A and C505CA only)

The C505A/C505CA includes a high performance / high speed 10-bit A/D-Converter (ADC) with 8 analog input channels. It operates with a successive approximation technique and uses self calibration mechanisms for reduction and compensation of offset and linearity errors. The A/D converter provides the following features:

- 8 multiplexed input channels (port 1), which can also be used as digital inputs/outputs
- 10-bit resolution
- Single or continuous conversion mode
- Internal start-of-conversion trigger capability
- Interrupt request generation after each conversion
- Using successive approximation conversion technique via a capacitor array
- Built-in hidden calibration of offset and linearity errors

The 10-bit ADC uses two clock signals for operation : the conversion clock f_{ADC} (=1/ t_{ADC}) and the input clock f_{IN} (=1/ t_{IN}). f_{ADC} is derived from the C505 system clock f_{OSC} which is applied at the XTAL pins. The input clock f_{IN} is equal to f_{OSC} The conversion f_{ADC} clock is limited to a maximum frequency of 2 MHz. Therefore, the ADC clock prescaler must be programmed to a value which assures that the conversion clock does not exceed 2 MHz. The prescaler ratio is selected by the bits ADCL1 and ADCL0 of SFR ADCON1.

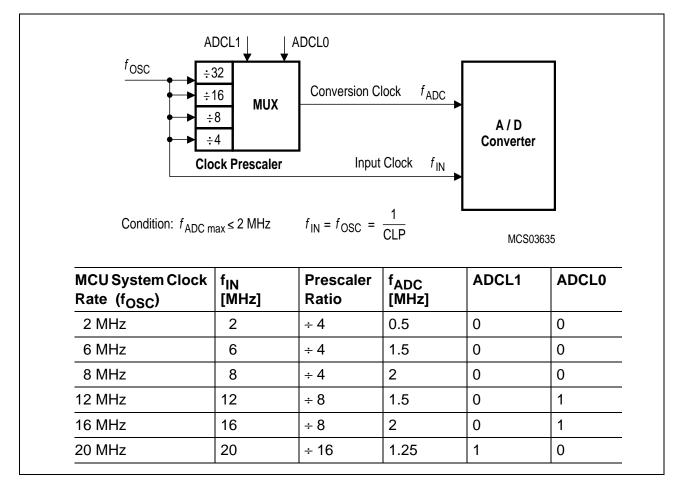


Figure 19 10-Bit A/D Converter Clock Selection

Data Sheet 40 12.00



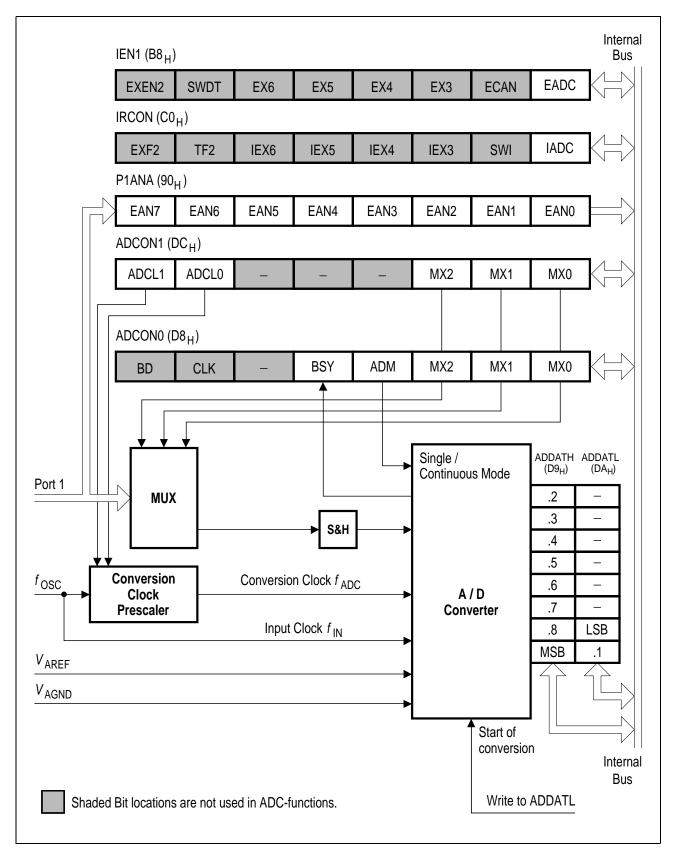


Figure 20 Block Diagram of the 10-Bit A/D Converter

Data Sheet 41 12.00



Interrupt System

The C505 provides 12 interrupt vectors with four priority levels. Five interrupt requests can be generated by the on-chip peripherals (timer 0, timer 1, timer 2, serial interface, A/D converter). One interrupt can be generated by the CAN controller (C505C and C505CA only) or by a software setting and in this case the interrupt vector is the same. Six interrupts may be triggered externally (P3.2/INT0, P3.3/INT1, P1.0/AN0/INT3/CC0, P1.1/AN1/INT4/CC1, P1.2/AN2/INT5/CC2, P1.3/AN3/INT6/CC3). Additionally, the P1.5/AN5/T2EX can trigger an interrupt. The wake-up from power-down mode interrupt has a special functionality which allows to exit from the software power-down mode by a short low pulse at either pin P3.2/INT0 or the pin P4.1/RXDC.

Figure 21 to Figure 23 give a general overview of the interrupt sources and illustrate the request and the control flags which are described in the next sections. Table 9 lists all interrupt sources with their request flags and interrupt vector addresses.

Table 9
Interrupt Source and Vectors

Interrupt Source	Interrupt Vector Address	Interrupt Request Flags
External Interrupt 0	0003 _H	IE0
Timer 0 Overflow	000B _H	TF0
External Interrupt 1	0013 _H	IE1
Timer 1 Overflow	001B _H	TF1
Serial Channel	0023 _H	RI / TI
Timer 2 Overflow / Ext. Reload	002B _H	TF2 / EXF2
A/D Converter	0043 _H	IADC
CAN Controller / Software Interrupt	004B _H	-/SWI
External interrupt 3	0053 _H	IEX3
External Interrupt 4	005B _H	IEX4
External Interrupt 5	0063 _H	IEX5
External interrupt 6	006B _H	IEX6
Wake-up from power-down mode	007B _H	_

Data Sheet 42 12.00



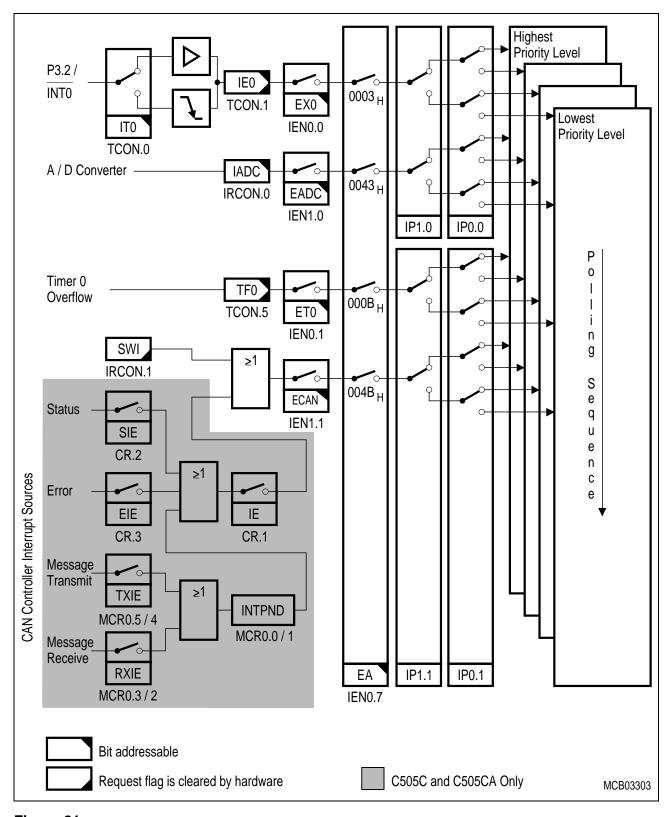


Figure 21
Interrupt Structure, Overview Part 1

Note: Each of the 15 CAN controller message objects (C505C and C505CA only), shown in the shaded area of **Figure 21** provides the bits/flags.

Data Sheet 43 12.00



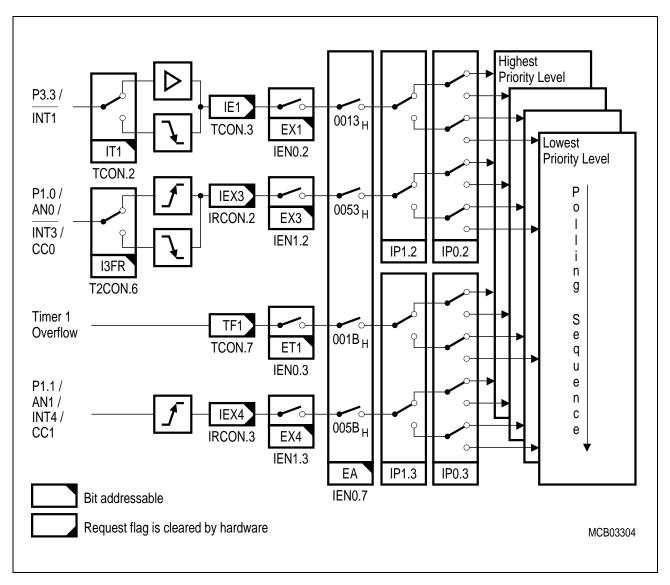


Figure 22 Interrupt Structure, Overview Part 2

Data Sheet 44 12.00



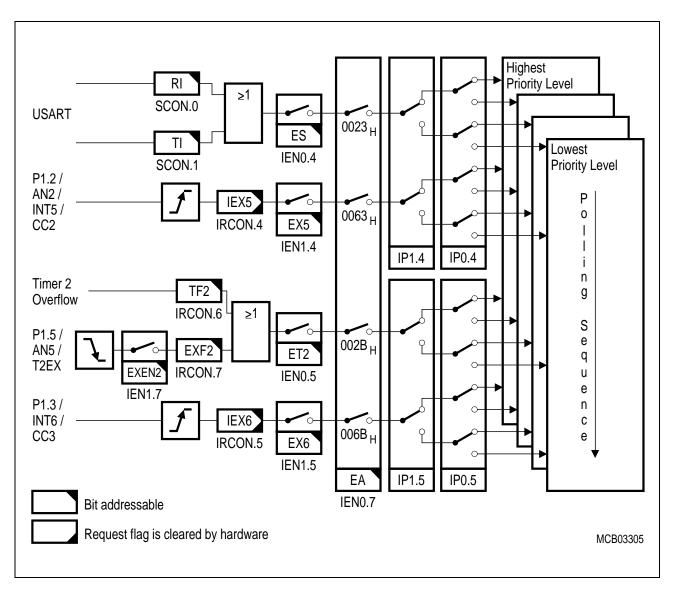


Figure 23 Interrupt Structure, Overview Part 3

Data Sheet 45 12.00



Fail Save Mechanisms

The C505 offers enhanced fail safe mechanisms, which allow an automatic recovery from software upset or hardware failure:

- a programmable watchdog timer (WDT), with variable time-out period from 192 μ s up to approx. 393.2 ms at 16 MHz (314.5 ms at 20 MHz).
- an oscillator watchdog (OWD) which monitors the on-chip oscillator and forces the microcontroller into reset state in case the on-chip oscillator fails; it also provides the clock for a fast internal reset after power-on.

The watchdog timer in the C505 is a 15-bit timer, which is incremented by a count rate of $f_{\rm OSC}/12$ upto $f_{\rm OSC}/192$. The system clock of the C505 is divided by two prescalers, a divide-by-two and a divide-by-16 prescaler. For programming of the watchdog timer overflow rate, the upper 7 bits of the watchdog timer can be written. **Figure 24** shows the block diagram of the watchdog timer unit.

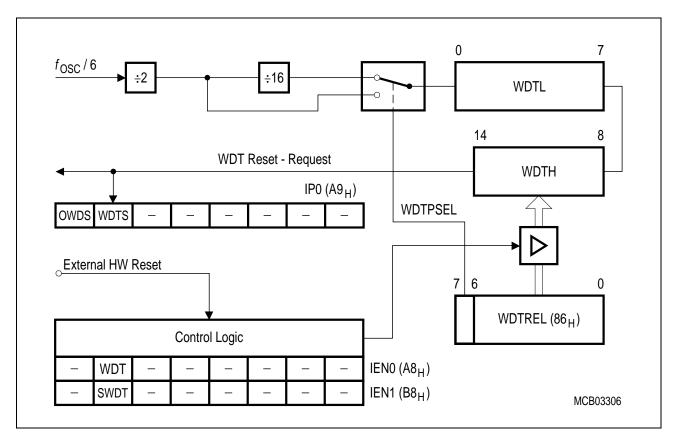


Figure 24
Block Diagram of the Programmable Watchdog Timer

The watchdog timer can be started by software (bit SWDT in SFR IEN1) but it cannot be stopped during active mode of the device. If the software fails to refresh the running watchdog timer an internal reset will be initiated on watchdog timer overflow. For refreshing of the watchdog timer the content of the SFR WDTREL is transferred to the upper 7-bit of the watchdog timer. The refresh sequence consists of two consequtive instructions which set the bits WDT and SWDT each. The reset cause (external reset or reset caused by the watchdog) can be examined by software (flag WDTS). It must be noted, however, that the watchdog timer is halted during the idle mode and power down mode of the processor.

Data Sheet 46 12.00



Oscillator Watchdog

The oscillator watchdog unit serves for three functions:

Monitoring of the on-chip oscillator's function

The watchdog supervises the on-chip oscillator's frequency; if it is lower than the frequency of the auxiliary RC oscillator in the watchdog unit, the internal clock is supplied by the RC oscillator and the device is brought into reset; if the failure condition disappears (i.e. the on-chip oscillator has a higher frequency than the RC oscillator), the part, in order to allow the oscillator to stabilize, executes a final reset phase of typ. 1 ms; then the oscillator watchdog reset is released and the part starts program execution from address 0000_H again.

- Fast internal reset after power-on

The oscillator watchdog unit provides a clock supply for the reset before the on-chip oscillator has started. The oscillator watchdog unit also works identically to the monitoring function.

- Control of external wake-up from software power-down mode

When the power-down mode is left by a low level at the P3.2/INTO pin or the P4.1/RXDC pin, the oscillator watchdog unit assures that the microcontroller resumes operation (execution of the power-down wake-up interrupt) with the nominal clock rate. In the power-down mode the RC oscillator and the on-chip oscillator are stopped. Both oscillators are started again when power-down mode is released. When the on-chip oscillator has a higher frequency than the RC oscillator, the microcontroller starts program execution by processing a power down interrupt after a final delay of typ. 1 ms in order to allow the on-chip oscillator to stabilize.

Data Sheet 47 12.00



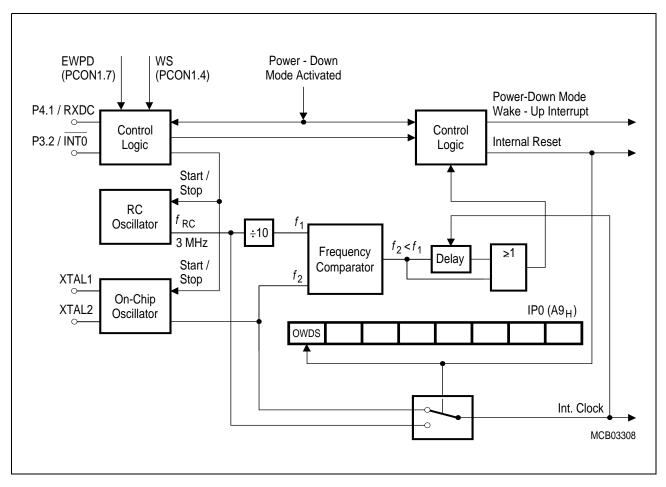


Figure 25
Functional Block Diagram of the Oscillator Watchdog

Data Sheet 48 12.00



Power Saving Modes

The C505 provides two basic power saving modes, the idle mode and the power down mode. Additionally, a slow down mode is available. This power saving mode reduces the internal clock rate in normal operating mode and it can be also used for further power reduction in idle mode.

- Idle mode

In the idle mode the main oscillator of the C505 continues to run, but the CPU is gated off from the clock signal. All peripheral units are further provided with the clock. The CPU status is preserved in its entirety. The idle mode can be terminated by any enabled interrupt of a peripheral unit or by a hardware reset.

Power down mode

The operation of the C505 is completely stopped and the oscillator is turned off. This mode is used to save the contents of the internal RAM with a very low standby current. Power down mode is entered by software and can be left by reset or by a short low pulse at pin P3.2/INTO.or P4.1/RXDC.

- Slow down mode

The controller keeps up the full operating functionality, but its normal clock frequency is internally divided by 32. This slows down all parts of the controller, the CPU and all peripherals, to 1/32-th of their normal operating frequency. Slowing down the frequency significantly reduces power consumption.

In the power down mode of operation, $V_{\rm DD}$ can be reduced to minimize power consumption. It must be ensured, however, that $V_{\rm DD}$ is not reduced before the power down mode is invoked, and that $V_{\rm DD}$ is restored to its normal operating level, before the power down mode is terminated. **Table 10** gives a general overview of the entry and exit procedures of the power saving modes.

Table 10 Power Saving Modes Overview

Mode	Entering (Instruction Example)	Leaving by	Remarks
Idle Mode	ORL PCON, #01H ORL PCON, #20H	Ocurrence of an interrupt from a peripheral unit	CPU clock is stopped; CPU maintains their data; peripheral units are active (if
		Hardware Reset	enabled) and provided with clock
Power Down Mode	ORL PCON, #02H	Hardware Reset	Oscillator is stopped;
	ORL PCON, #40H	Short low pulse at pin P3.2/INT0 or P4.1/RXDC	contents of on-chip RAM and SFR's are maintained;
Slow Down Mode	ORL PCON,#10H	ANL PCON,#0EFH or Hardware Reset	Oscillator frequency is reduced to 1/32 of its nominal frequency

Data Sheet 49 12.00



OTP Memory Operation (C505A-4E and C505CA-4E only)

The C505A-4E/C505CA-4E contains a 32K byte one-time programmable (OTP) program memory. With the C505A-4E/C505CA-4E fast programming cycles are achieved (1 byte in 100 μ sec). Also several levels of OTP memory protection can be selected.

For programming of the device, the C505A-4E/C505CA-4E must be put into the programming mode. This typically is done not in-system but in a special programming hardware. In the programming mode the C505A-4E/C505CA-4E operates as a slave device similar as an EPROM standalone memory device and must be controlled with address/data information, control lines, and an external 11.5V programming voltage. **Figure 26** shows the pins of the C505A-4E/C505CA-4E which are required for controlling of the OTP programming mode.

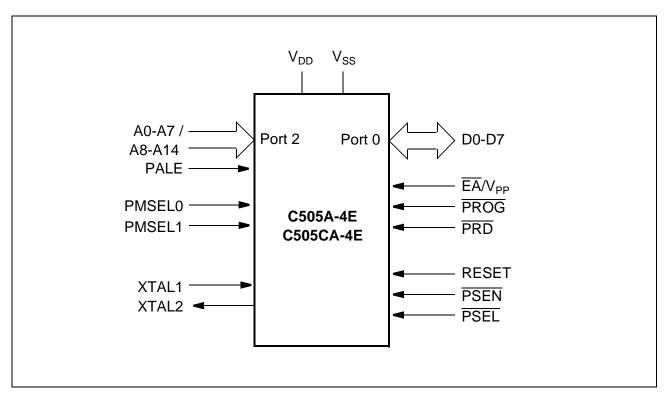


Figure 26
Programming Mode Configuration

Data Sheet 50 12.00



Pin Configuration in Programming Mode

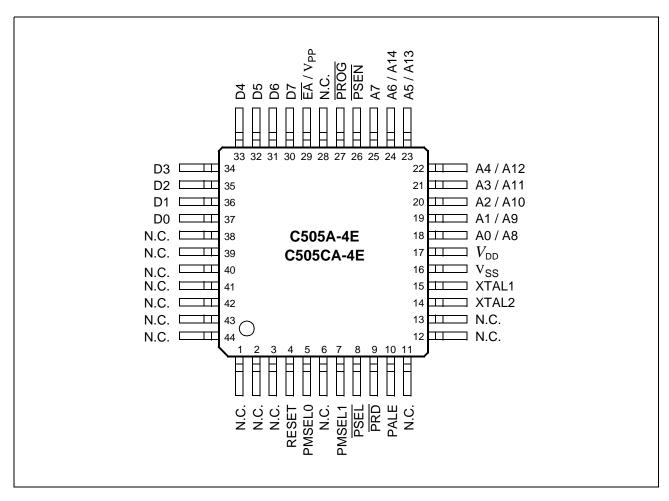


Figure 27
P-MQFP-44 Pin Configuration of the C505A-4E/C505CA-4E in Programming Mode (Top View)

Data Sheet 51 12.00



The following **Table 11** contains the functional description of all C505A-4E/C505CA-4E pins which are required for OTP memory programming.

Table 11
Pin Definitions and Functions in Programming Mode

Symbol	Pin Number	I/O *)	Function				
RESET	4	I	Reset This input must be at static "1" (active) level during the whole programming mode.				
PMSEL0 PMSEL1	5 7	I I	Programming mode selection pins These pins are used to select the different access mode programming mode. PMSEL1,0 must satisfy a setup time rising edge of PALE. When the logic level of PMSEL1,0 changed, PALE must be at low level.				
			PMSEL1	PMSEL0	Access Mode		
			0	0	Reserved		
			0	1	Read version bytes		
			1	0	Program/read lock bits		
			1	1	Program/read OTP memory byte		
PSEL	8	I	Basic programming mode select This input is used for the basic programming mode selection and must be switched according Figure 28.				
PRD	9	I	Programming mode read strobe This input is used for read access control for OTP memory read, Version Register read, and lock bit read operations.				
PALE	10	I	Programming address latch enable PALE is used to latch the high address lines. The high address lines must satisfy a setup and hold time to/from the falling edge of PALE. PALE must be at low level when the logic level of PMSEL1,0 is changed.				
XTAL2	14	0	XTAL2 Output of the	e inverting osc	cillator amplifier.		
XTAL1	15	I	XTAL1 Input to the oscillator amplifier.				
V_{SS}	16	-	Circuit ground potential must be applied in programming mode.				
V_{DD}	17	-	Power supp	oly terminal lied in prograi	mming mode.		

^{*)} I = Input

Data Sheet 52 12.00

O= Output



Table 11
Pin Definitions and Functions in Programming Mode (cont'd)

Symbol	Pin Number	I/O *)	Function
P2.0-7	18-25	I	Address lines P2.0-7 are used as multiplexed address input lines A0-A7 and A8-A14. A8-A14 must be latched with PALE.
PSEN	26	I	Program store enable This input must be at static "0" level during the whole programming mode.
PROG	27	I	Programming mode write strobe This input is used in programming mode as a write strobe for OTP memory program, and lock bit write operations During basic programming mode selection a low level must be applied to PROG.
EA/V _{PP}	29	_	External Access / Programming voltage This pin must be at 11.5V (V _{PP}) voltage level during programming of an OTP memory byte or lock bit. During an OTP memory read operation this pin must be at V _{IH} high level. This pin is also used for basic programming mode selection. At basic programming mode selection a low level must be applied to EA/V _{PP} .
D7-0	30-37	I/O	Data lines 0-7 During programming mode, data bytes are transferred via the bidirectional port 0 data lines.
N.C.	1-3, 6, 11-13, 28, 38-44	_	Not Connected These pins should not be connected in programming mode.

^{*)} I = Input

O= Output

Data Sheet 53 12.00



Basic Programming Mode Selection

The basic programming mode selection scheme is shown in Figure 28.

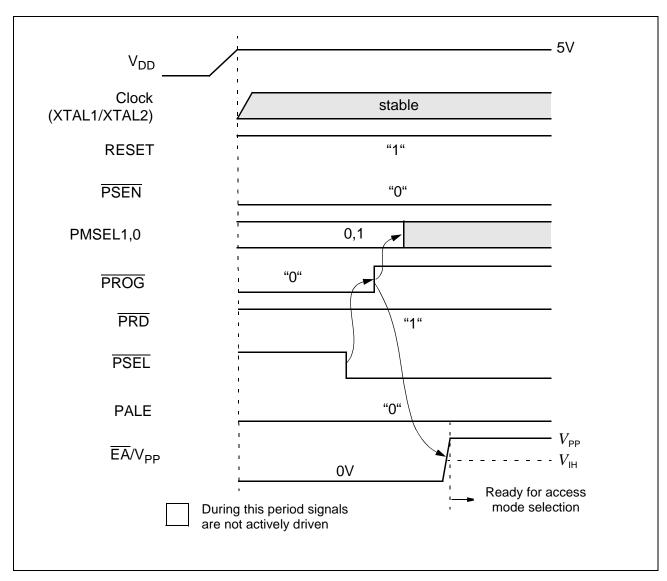


Figure 28
Basic Programming Mode Selection

Data Sheet 54 12.00



Table 12
Access Modes Selection

Acces Made	EA/	BBGG	<u> </u>	PMSEL		Address	Data	
Access Mode	V_{PP}	PROG	PRD	1	0	(Port 2)	(Port 0)	
Program OTP memory byte	V_{PP}	<u> </u>	Н	Н	Н	A0-7	D0-7	
Read OTP memory byte	V _{IH}	Н	7			A8-14		
Program OTP lock bits	V_{PP}	ЪГ	Н	Н	L	_	D1,D0 see	
Read OTP lock bits	V _{IH}	Н	7				Table 13	
Read OTP version byte	V _{IH}	Н		L	Н	Byte addr. of sign. byte	D0-7	

Lock Bits Programming / Read

The C505A-4E/C505CA-4E has two programmable lock bits which, when programmed according to **Table 13**, provide four levels of protection for the on-chip OTP code memory. The state of the lock bits can also be read.

Table 13 Lock Bit Protection Types

Lock B	Bits at D1,D0	Protection	Protection Type
D1	D0	Level	
1	1	Level 0	The OTP lock feature is disabled. During normal operation of the C505A-4E/C505CA-4E, the state of the $\overline{\text{EA}}$ pin is not latched on reset.
1	0	Level 1	During normal operation of the C505A-4E/C505CA-4E, MOVC instructions executed from external program memory are disabled from fetching code bytes from internal memory. EA is sampled and latched on reset. An OTP memory read operation is only possible using the ROM/OTP verification mode 2 for protection level 1. Further programming of the OTP memory is disabled (reprogramming security).
0	1	Level 2	Same as level 1, but also OTP memory read operation using OTP verification mode is disabled.
0	0	Level 3	Same as level 2; but additionally external code execution by setting EA=low during normal operation of the C505A-4E/C505CA-4E is no more possible. External code execution, which is initiated by an internal program (e.g. by an internal jump instruction above the ROM boundary), is still possible.

Data Sheet 55 12.00



Absolute Maximum Ratings

Parameter	Symbol	Limit '	Limit Values		Notes
		min.	max.		
Storage temperature	$T_{ m ST}$	– 65	150	°C	_
Voltage on $V_{\rm DD}$ pins with respect to ground ($V_{\rm SS}$)	V_{DD}	- 0.5	6.5	V	_
Voltage on any pin with respect to ground ($V_{\rm SS}$)	V_{IN}	- 0.5	V _{DD} + 0.5	V	_
Input current on any pin during overload condition		– 10	10	mA	_
Absolute sum of all input currents during overload condition			100 mA	mA	_
Power dissipation	P_{DISS}		1	W	_

Note: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage of the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for longer periods may affect device reliability. During absolute maximum rating overload conditions $(V_{IN} > V_{DD})$ or $V_{IN} < V_{SS}$ the voltage on V_{DD} pins with respect to ground (V_{SS}) must not exceed the values defined by the absolute maximum ratings.

Data Sheet 56 12.00



Operating Conditions

Parameter	Symbol	Limit	Values	Unit	Notes
		min.	max.		
Supply voltage	V_{DD}	4.25	5.5	V	Active mode,
					f _{osc max} = 20 MHz
		2	5.5	V	PowerDown mode
Ground voltage	V _{SS}	0		٧	Reference voltage
Ambient temperature				°C	_
SAB-C505	T_{A}	0	70		
SAF-C505	T_{A}	-40	85		
SAH-C505	T_{A}	-40	110		
SAK-C505	T_{A}	-40	125		
Analog reference voltage	V_{AREF}	4	V _{DD} + 0.1	V	-
Analog ground voltage	V_{AGND}	V _{SS} - 0.1	V _{SS} + 0.2	V	_
Analog input voltage	V_{AIN}	V_{AGND} -0.2	V_{AREF} +0.2	V	_
XTAL clock	f _{osc}	2	20 (with 50% duty cycle)	MHz	1)

¹⁾ For the extended temperature range -40 °C to 110 °C (SAH) and -40 °C to 125 °C (SAK), the devices C505-2R, C505-L, C505C-2R and C505C-L have the max. operating frequency of 16MHz with 50% clock duty cycle.

Parameter Interpretation

The parameters listed in the following partly represent the characteristics of the C505 and partly its demands on the system. To aid in interpreting the parameters right, when evaluating them for a design, they are marked in column "Symbol":

CC (Controller Characteristics):

The logic of the C505 will provide signals with the respective characteristics.

SR (System Requirement):

The external system must provide signals with the respective characteristics to the C505.

Data Sheet 57 12.00



DC Characteristics

(Operating Conditions apply)

Parameter	Symbol	Limit '	Values	Unit	Test Condition
		min.	max.		
Input low voltages all except EA, RESET EA pin RESET pin	$V_{ m IL} \ V_{ m IL1} \ V_{ m IL2}$	- 0.5 - 0.5 - 0.5	$0.2 \ V_{\rm DD} - 0.1 \\ 0.2 \ V_{\rm DD} - 0.3 \\ 0.2 \ V_{\rm DD} + 0.1$	V V	_ _ _
Input high voltages all except XTAL1, RESET XTAL1 pin RESET pin	$V_{IH} \ V_{IH1} \ V_{IH2}$	$0.2 \ V_{\rm DD} + 0.9 \\ 0.7 \ V_{\rm DD} \\ 0.6 \ V_{\rm DD}$	$V_{\rm DD}$ + 0.5 $V_{\rm DD}$ + 0.5 $V_{\rm DD}$ + 0.5	V V	- - -
Output low voltages Ports 1, 2, 3, 4 Port 0, ALE, PSEN	$V_{ m OL} \ V_{ m OL1}$	_ _	0.45 0.45	V V	$I_{\rm OL}$ = 1.6 mA ¹⁾ $I_{\rm OL}$ = 3.2 mA ¹⁾
Output high voltages Ports 1, 2, 3, 4	V_{OH}	2.4 0.9 V _{DD}		V	$I_{OH} = -80 \mu A$ $I_{OH} = -10 \mu A$
Port 0 in external bus mode, ALE, PSEN	V_{OH2}	2.4 0.9 V _{DD}		V V	$I_{OH} = -800 \mu\text{A}$ $I_{OH} = -80 \mu\text{A}^{2}$
Logic 0 input current Ports 1, 2, 3, 4	I_{IL}	- 10	- 70	μΑ	$V_{\rm IN} = 0.45 \ { m V}$
Logical 1-to-0 transition current Ports 1, 2, 3, 4	I_{TL}	- 65	- 650	μΑ	V _{IN} = 2 V
Input leakage current Port 0, AN0-7 (Port 1), EA	I_{LI}	_	± 1	μΑ	$0.45 < V_{IN} < V_{DD}$
Input high current to RESET	I_{IH}	5	100	μΑ	$0.6 \ V_{\rm DD} \!<\! V_{\rm IN} \!<\! V_{\rm DD}$
Pin capacitance	C_{IO}	_	10	pF	$f_{\rm c}$ = 1 MHz, $T_{\rm A}$ = 25 °C
Overload current	I_{OV}	_	±5	mA	3) 4)
Programming voltage	$V_{\sf PP}$	10.9	12.1	V	11.5 V ± 5% ⁵⁾
Supply current at EA/V _{PP}			30	mA	6)

Notes see Page 60

Data Sheet 58 12.00



Power Supply Currents

Parameter			Symbol	Limit '	Values	Unit	Test Condition
			typ. ¹²⁾	max. ¹³⁾			
C505 / C505C	Active Mode	12 MHz 20 MHz	$I_{ m DD}$ $I_{ m DD}$	19.3 31.3	27.0 39	mA	7)
	Idle Mode	12 MHz 20 MHz	$I_{ m DD}$ $I_{ m DD}$	10.3 16.2	13.0 21.0	mA	8)
	Active Mode with slow-down enabled	12 MHz 20 MHz	$I_{ m DD}$ $I_{ m DD}$	3.9 4.8	5.5 7.5	mA	9)
	Idle Mode with slow-down enabled	12 MHz 20 MHz	$I_{ m DD}$ $I_{ m DD}$	3.2 4.0	5.0 7.0	mA	10)
	Power down mode		I_{PD}	10	50	μΑ	$V_{\rm DD}$ = 25.5 V ¹¹⁾
C505A-4E /C505CA-4E	Active Mode	16 MHz 20 MHz	$I_{ m DD}$ $I_{ m DD}$	28.7 35.2	30.7 37.6	mA	7)
	Idle Mode	16 MHz 20 MHz	$I_{ m DD}$ $I_{ m DD}$	14.9 17.7	15.9 18.9	mA	8)
	Active Mode with slow-down enabled	16 MHz 20 MHz	$I_{ m DD}$ $I_{ m DD}$	9.9 12.3	12.8 15.6	mA	9)
	Idle Mode with slow-down enabled	16 MHz 20 MHz	$I_{ m DD}$ $I_{ m DD}$	5.1 6.3	5.6 6.8	mA	10)
	Power down mode		I_{PD}	5.6	20	μΑ	$V_{\rm DD}$ = 25.5 V ¹¹⁾
C505A-4R / C505CA-4R	Active Mode	16 MHz 20 MHz	$I_{ extsf{DD}}$ $I_{ extsf{DD}}$	22.8 27.6	29.2 35.3	mA	7)
/C505A-2R / C505CA-2R /C505A-L / C505CA-L	Idle Mode	16 MHz 20 MHz	$I_{ m DD}$ $I_{ m DD}$	12.7 15.0	16.3 19.3	mA	8)
	Active Mode with slow-down enabled	16 MHz 20 MHz	$I_{ m DD}$ $I_{ m DD}$	6.6 7.3	8.2 9.3	mA	9)
	Idle Mode with slow-down enabled	16 MHz 20 MHz	$I_{ m DD}$ $I_{ m DD}$	5.0 5.3	5.9 6.5	mA	10)
	Power down mode		I_{PD}	5.3	30	μΑ	$V_{\rm DD}$ = 25.5 V ¹¹⁾

Notes see Page 60

Data Sheet 59 12.00



Note:

- 1) Capacitive loading on ports 0 and 2 may cause spurious noise pulses to be superimposed on the V_{OL} of ALE and port 3. The noise is due to external bus capacitance discharging into the port 0 and port 2 pins when these pins make 1-to-0 transitions during bus operation. In the worst case (capacitive loading > 100 pF), the noise pulse on ALE line may exceed 0.8 V. In such cases it may be desirable to qualify ALE with a schmitt-trigger, or use an address latch with a schmitt-trigger strobe input.
- 2) Capacitive loading on ports 0 and 2 may cause the $V_{\rm OH}$ on ALE and $\overline{\rm PSEN}$ to momentarily fall below the 0.9 $V_{\rm DD}$ specification when the address lines are stabilizing.
- 3) Overload conditions under operating conditions occur if the voltage on the respective pin exceeds the specified operating range (i.e. $V_{\rm OV} > V_{\rm DD} + 0.5$ V or $V_{\rm OV} < V_{\rm SS}$ 0.5 V). The absolute sum of input currents on all port pins may not exceed 50 mA. The supply voltage $V_{\rm DD}$ and $V_{\rm SS}$ must remain within the specified limits.
- 4) Not 100% tested, guaranteed by design characterization.
- 5) Only valid for C505A-4E and C505CA-4E.
- 6) Only valid for C505A-4E and C505CA-4E in programming mode.
- 7) $I_{\rm DD}$ (active mode) is measured with: XTAL1 driven with $t_{\rm R}$, $t_{\rm F}$ = 5 ns, 50% duty cycle , $V_{\rm IL}$ = $V_{\rm SS}$ + 0.5 V, $V_{\rm IH}$ = $V_{\rm DD}$ 0.5 V; XTAL2 = N.C.; $\overline{\rm EA}$ = Port 0 = RESET = $V_{\rm DD}$; all other pins are disconnected.
- 8) $I_{\rm DD}$ (idle mode) is measured with all output pins disconnected and with all peripherals disabled; XTAL1 driven with $t_{\rm R}$, $t_{\rm F}$ = 5 ns, 50% duty cycle, $V_{\rm IL}$ = $V_{\rm SS}$ + 0.5 V, $V_{\rm IH}$ = $V_{\rm DD}$ 0.5 V; XTAL2 = N.C.; RESET = $\overline{\rm EA}$ = $V_{\rm SS}$; Port0 = $V_{\rm DD}$; all other pins are disconnected; the microcontroller is put into idle mode by software;
- 9) $I_{\rm DD}$ (active mode with slow-down mode) is measured with all output pins disconnected and with all peripherals disabled; XTAL1 driven with $t_{\rm R}$, $t_{\rm F}$ = 5 ns, 50% duty cycle, $V_{\rm IL}$ = $V_{\rm SS}$ + 0.5 V, $V_{\rm IH}$ = $V_{\rm DD}$ 0.5 V; XTAL2 = N.C.; RESET = $\overline{\rm EA}$ = $V_{\rm SS}$; all other pins are disconnected; the microcontroller is put into slow-down mode by software;
- 10) $I_{
 m DD}$ (idle mode with slow-down mode) is measured with all output pins disconnected and with all peripherals disabled:
 - XTAL1 driven with $t_{\rm R}$, $t_{\rm F}$ = 5 ns, 50% duty cycle, $V_{\rm IL}$ = $V_{\rm SS}$ + 0.5 V, $V_{\rm IH}$ = $V_{\rm DD}$ 0.5 V; XTAL2 = N.C.; RESET = $\overline{\rm EA}$ = $V_{\rm SS}$; Port0 = $V_{\rm DD}$; all other pins are disconnected; the microcontroller is put into idle mode with slow-down enabled by software;
- 11) I_{PD} (power-down mode) is measured under following conditions: Port $0 = \overline{EA} = V_{DD}$; RESET $=V_{SS}$; XTAL2 = N.C.; XTAL1 $=V_{SS}$; $V_{AGND} = V_{SS}$; $V_{AREF} = V_{DD}$; all other pins are disconnected.
- 12) The typical $I_{\rm DD}$ values are periodically measured at $T_{\rm A}$ = +25 °C but not 100% tested.
- 13) The maximum $I_{\rm DD}$ values are measured under worst case conditions ($T_{\rm A}$ = 0 °C or -40 °C and $V_{\rm DD}$ = 5.5 V)
- 14) The values are valid for C505CA-4R, C505CA-2R, C505CA-L, C505A-4R, C505A-2R and C505A-L only.

Data Sheet 60 12.00



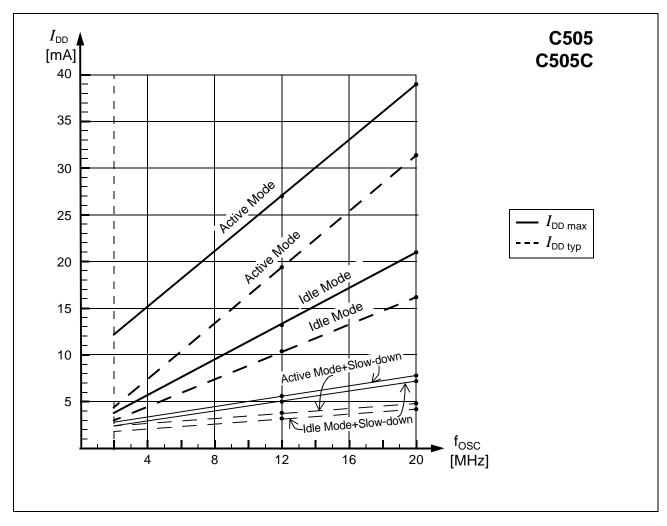


Figure 29 I_{DD} Diagram of C505 and C505C

C505/C505C: Power Supply Current Calculation Formulas

Parameter	Symbol	Formula
Active mode	$I_{ m DD\ typ} \ I_{ m DD\ max}$	1.5 * f_{OSC} + 1.3 1.5 * f_{OSC} + 9.0
Idle mode	$I_{ m DD\ typ} \ I_{ m DD\ max}$	$0.74 * f_{OSC} + 1.4$ $1.0 * f_{OSC} + 1.0$
Active mode with slow-down enabled	$I_{ m DD\ typ} \ I_{ m DD\ max}$	$0.11 * f_{OSC} + 2.6$ $0.25 * f_{OSC} + 2.5$
Idle mode with slow-down enabled	$I_{ m DD\ typ} \ I_{ m DD\ max}$	$0.1 * f_{OSC} + 2.0$ $0.25 * f_{OSC} + 2.0$

Note: $f_{\rm osc}$ is the oscillator frequency in MHz. $I_{\rm DD}$ values are given in mA.

Data Sheet 61 12.00



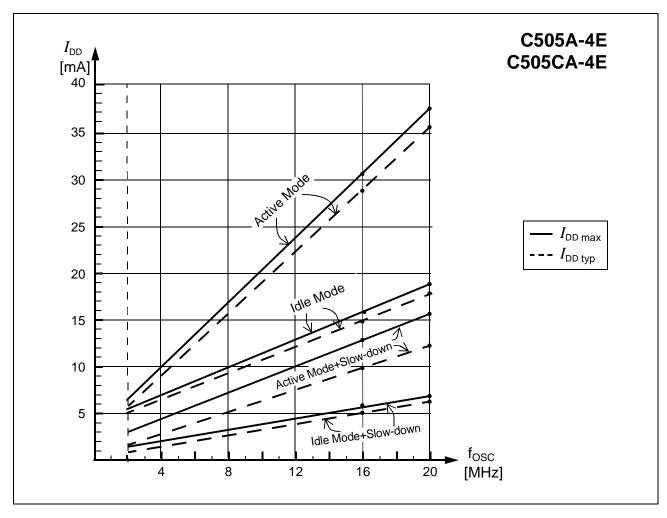


Figure 30 I_{DD} Diagram of C505A-4E and C505CA-4E

C505A-4E/C505CA-4E: Power Supply Current Calculation Formulas

Parameter	Symbol	Formula
Active mode	$I_{ m DD\ typ} \ I_{ m DD\ max}$	$1.63 * f_{OSC} + 2.6$ $1.74 * f_{OSC} + 2.8$
Idle mode	$I_{ m DD\ typ} \ I_{ m DD\ max}$	$0.69 * f_{OSC} + 3.9$ $0.74 * f_{OSC} + 4.1$
Active mode with slow-down enabled	$I_{ m DD\ typ} \ I_{ m DD\ max}$	$0.6 * f_{OSC} + 0.3$ $0.7 * f_{OSC} + 1.6$
Idle mode with slow-down enabled	$I_{ m DD\ typ}$ $I_{ m DD\ max}$	$0.3 * f_{OSC} + 0.3$ $0.3 * f_{OSC} + 0.8$

Note: $f_{\rm osc}$ is the oscillator frequency in MHz. $I_{\rm DD}$ values are given in mA.

Data Sheet 62 12.00



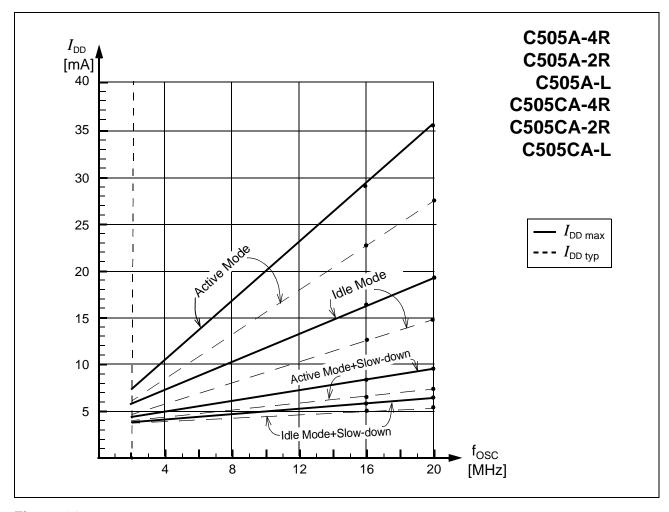


Figure 31 I_{DD} Diagram of C505A-4R/C505A-2R/C505A-L/C505CA-4R/C505CA-2R/C505CA-L

C505A-4R/C505A-2R/C505A-L/C505CA-4R/C505CA-2R/C505CA-L: Power Supply Current Calculation Formulas

Parameter	Symbol	Formula
Active mode	$I_{\rm DD\ typ} \\ I_{\rm DD\ max}$	1.19 * f_{OSC} + 3.77 1.54 * f_{OSC} + 4.47
Idle mode	$I_{ m DD\ typ} \ I_{ m DD\ max}$	$0.57 * f_{OSC} + 3.55$ $0.75 * f_{OSC} + 4.26$
Active mode with slow-down enabled	$I_{ m DD\ typ} \ I_{ m DD\ max}$	$0.18 * f_{OSC} + 3.74$ $0.28 * f_{OSC} + 3.67$
Idle mode with slow-down enabled	$I_{ m DD\ typ}$ $I_{ m DD\ max}$	$0.07 * f_{OSC} + 3.91$ $0.14 * f_{OSC} + 3.64$

Note: f_{osc} is the oscillator frequency in MHz. I_{DD} values are given in mA.

Data Sheet 63 12.00



A/D Converter Characteristics of C505 and C505C

(Operating Conditions apply)

Parameter	Symbol	Limit	Limit Values		Test Condition
		min.	max.		
Analog input voltage	V_{AIN}	V _{AGND} - 0.2	V _{AREF} + 0.2	V	1)
Sample time	$t_{\mathbb{S}}$	_	$64 \times t_{IN} 32 \times t_{IN} 16 \times t_{IN} 8 \times t_{IN}$	ns	Prescaler ÷ 32 Prescaler ÷ 16 Prescaler ÷ 8 Prescaler ÷ 4
Conversion cycle time	t_{ADCC}	_	$320 \times t_{\text{IN}}$ $160 \times t_{\text{IN}}$ $80 \times t_{\text{IN}}$ $40 \times t_{\text{IN}}$	ns	Prescaler ÷ 32 Prescaler ÷ 16 Prescaler ÷ 8 Prescaler ÷ 4 3)
Total unadjusted error	$T_{\sf UE}$	_	± 2	LSB	$V_{SS}+0.5V \le V_{AIN} \le V_{DD}-0.5V^{4}$
Internal resistance of reference voltage source	R_{AREF}	_	<i>t</i> _{ADC} / 500 - 1	kΩ	t _{ADC} in [ns] ^{5) 6)}
Internal resistance of analog source	R_{ASRC}	_	<i>t</i> _S / 500 - 1	kΩ	t _S in [ns] ^{2) 6)}
ADC input capacitance	C_{AIN}	_	50	pF	6)

Notes see next page.

Clock calculation table:

Clock Prescaler Ratio	ADCL	_1, 0	tADC	t _S	tADCC
÷ 32	1	1	32 x t _{IN}	64 x t _{IN}	320 x t _{IN}
÷ 16	1	0	16 x t _{IN}	32 x t _{IN}	160 x t _{IN}
÷ 8	0	1	8 x t _{IN}	16 x t _{IN}	80 x t _{IN}
÷ 4	0	0	4 x t _{IN}	8 x t _{IN}	40 x t _{IN}

Further timing conditions : t_{ADC} min = 800 ns t_{IN} = 1 / t_{OSC} = t_{CLP}

Data Sheet 64 12.00

C505/C505C/C505A/C505CA



Note:

- 1) V_{AIN} may exeed V_{AGND} or V_{AREF} up to the absolute maximum ratings. However, the conversion result in these cases will be 00_H or FF_H , respectively.
- 2) During the sample time the input capacitance C_{AIN} must be charged/discharged by the external source. The internal resistance of the analog source must allow the capacitance to reach their final voltage level within t_S. After the end of the sample time t_S, changes of the analog input voltage have no effect on the conversion result.
- 3) This parameter includes the sample time t_S, the time for determining the digital result. Values for the conversion clock t_{ADC} depend on programming and can be taken from the table on the previous page.
- 4) T_{UE} (max.) is tested at $-40 \le T_A \le 125$ °C; $V_{DD} \le 5.5$ V; $V_{AREF} \le V_{DD} + 0.1$ V and $V_{SS} \le V_{AGND}$. It is guaranteed by design characterization for all other voltages within the defined voltage range. If an overload condition occurs on maximum 2 unused analog input pins and the absolute sum of input overload currents on all analog input pins does not exceed 10 mA, an additional conversion error of 1/2 LSB is permissible.
- 5) During the conversion the ADC's capacitance must be repeatedly charged or discharged. The internal resistance of the reference source must allow the capacitance to reach their final voltage level within the indicated time. The maximum internal resistance results from the programmed conversion timing.
- 6) Not 100% tested, but guaranteed by design characterization.

Data Sheet 65 12.00



A/D Converter Characteristics of C505A and C505CA

(Operating Conditions apply)

Parameter	Symbol	Limit	Values	Unit	Test Condition
		min.	max.		
Analog input voltage	V_{AIN}	V_{AGND}	V_{AREF}	V	1)
Sample time	ts	_	64 x t _{IN} 32 x t _{IN} 16 x t _{IN} 8 x t _{IN}	ns	Prescaler ÷ 32 Prescaler ÷ 16 Prescaler ÷ 8 Prescaler ÷ 4 2)
Conversion cycle time	t _{ADCC}	_	384 x t _{IN} 192 x t _{IN} 96 x t _{IN} 48 x t _{IN}	ns	Prescaler ÷ 32 Prescaler ÷ 16 Prescaler ÷ 8 Prescaler ÷ 4 3)
Total unadjusted error	$T_{\sf UE}$	_	± 2	LSB	$V_{SS}+0.5V \le V_{AIN} \le V_{DD}-0.5V^{4}$
		_	± 4	LSB	$\begin{array}{c} V_{\rm SS} < V_{\rm AIN} < V_{\rm DD} + 0.5 \mathrm{V} \\ V_{\rm DD} - 0.5 \mathrm{V} < V_{\rm AIN} < V_{\rm DD} \end{array} \label{eq:VSS} \ ^{4)}$
Internal resistance of reference voltage source	R_{AREF}	_	t _{ADC} / 250 - 0.25	kΩ	t _{ADC} in [ns] ^{5) 6)}
Internal resistance of analog source	R_{ASRC}	_	t _S / 500 - 0.25	kΩ	t _S in [ns] ^{2) 6)}
ADC input capacitance	C_{AIN}	_	50	pF	6)

Notes see next page.

Clock calculation table:

Clock Prescaler Ratio	ADCL	.1, 0	^t ADC	t _S	tADCC
÷ 32	1	1	32 x t _{IN}	64 x t _{IN}	384 x t _{IN}
÷ 16	1	0	16 x t _{IN}	32 x t _{IN}	192 x t _{IN}
÷ 8	0	1	8 x t _{IN}	16 x t _{IN}	96 x t _{IN}
÷ 4	0	0	4 x t _{IN}	8 x t _{IN}	48 x t _{IN}

Further timing conditions : $t_{ADC} min = 500 ns$

 $t_{IN} = 1 / f_{OSC} = t_{CLP}$

Data Sheet 66 12.00

C505/C505C/C505A/C505CA



Note:

- 1) V_{AIN} may exeed V_{AGND} or V_{AREF} up to the absolute maximum ratings. However, the conversion result in these cases will be $X000_H$ or $X3FF_H$, respectively.
- 2) During the sample time the input capacitance C_{AIN} must be charged/discharged by the external source. The internal resistance of the analog source must allow the capacitance to reach their final voltage level within t_S. After the end of the sample time t_S, changes of the analog input voltage have no effect on the conversion result.
- 3) This parameter includes the sample time t_S, the time for determining the digital result and the time for the calibration. Values for the conversion clock t_{ADC} depend on programming and can be taken from the table on the previous page.
- 4) T_{UE} is tested at $V_{AREF} = 5.0 \text{ V}$, $V_{AGND} = 0 \text{ V}$, $V_{DD} = 4.9 \text{ V}$. It is guaranteed by design characterization for all other voltages within the defined voltage range. If an overload condition occurs on maximum 2 unused analog input pins and the absolute sum of input overload currents on all analog input pins does not exceed 10 mA, an additional conversion error of 1/2 LSB is permissible.
- 5) During the conversion the ADC's capacitance must be repeatedly charged or discharged. The internal resistance of the reference source must allow the capacitance to reach their final voltage level within the indicated time. The maximum internal resistance results from the programmed conversion timing.
- 6) Not 100% tested, but guaranteed by design characterization.

Data Sheet 67 12.00



AC Characteristics (16 MHz, 0.4 to 0.6 Duty Cycle)

(Operating Conditions apply)

(C_L for port 0, ALE and $\overline{\text{PSEN}}$ outputs = 100 pF; C_L for all other outputs = 80 pF)

Program Memory Characteristics

Parameter	Symbol		Limit Values				
		16-MHz clock Duty Cycle 0.4 to 0.6		Variable Clock 1/CLP= 2 MHz to 16 MHz			
		min.	max.	min.	max.		
ALE pulse width	t_{LHLL}	48	-	CLP - 15	_	ns	
Address setup to ALE	t_{AVLL}	10	_	TCL _{Hmin} -15	_	ns	
Address hold after ALE	t_{LLAX}	10	-	TCL _{Hmin} -15	_	ns	
ALE to valid instruction in	t_{LLIV}	_	75	_	2 CLP - 50	ns	
ALE to PSEN	t_{LLPL}	10	-	TCL _{Lmin} -15	_	ns	
PSEN pulse width	t_{PLPH}	73	_	CLP+ TCL _{Hmin} -15	_	ns	
PSEN to valid instruction in	t_{PLIV}	_	38	_	CLP+ TCL _{Hmin} - 50	ns	
Input instruction hold after PSEN	t_{PXIX}	0	_	0	_	ns	
Input instruction float after PSEN	$t_{PXIZ}^{*)}$	_	15	_	TCL _{Lmin} -10	ns	
Address valid after PSEN	t _{PXAV} *)	20	_	TCL _{Lmin} - 5	_	ns	
Address to valid instruction in	t _{AVIV}	_	95	_	2 CLP + TCL _{Hmin} -55	ns	
Address float to PSEN	t_{AZPL}	-5	-	-5	_	ns	

^{*)} Interfacing the C505 to devices with float times up to 20 ns is permissible. This limited bus contention will not cause any damage to port 0 drivers.

Data Sheet 68 12.00



AC Characteristics (16 MHz, 0.4 to 0.6 Duty Cycle, cont'd)

External Data Memory Characteristics

Parameter	Symbol	Limit Values				
		16-MHz clock Duty Cycle 0.4 to 0.6		Variable Clock 1/CLP= 2 MHz to 16 MHz		
		min.	max.	min.	max.	
RD pulse width	t_{RLRH}	158	_	3 CLP - 30	_	ns
WR pulse width	t _{WLWH}	158	_	3 CLP - 30	_	ns
Address hold after ALE	t _{LLAX2}	48	_	CLP - 15	_	ns
RD to valid data in	t_{RLDV}	_	100	_	2 CLP+ TCL _{Hmin} - 50	ns
Data hold after RD	t_{RHDX}	0	_	0	_	ns
Data float after RD	t_{RHDZ}	_	51	_	CLP - 12	ns
ALE to valid data in	t_{LLDV}	_	200	_	4 CLP - 50	ns
Address to valid data in	t_{AVDV}	_	200	_	4 CLP + TCL _{Hmin} -75	ns
ALE to WR or RD	t_{LLWL}	73	103	CLP + TCL _{Lmin} - 15	CLP+ TCL _{Lmin} + 15	ns
Address valid to WR	t_{AVWL}	95	_	2 CLP - 30	_	ns
WR or RD high to ALE high	t _{WHLH}	10	40	TCL _{Hmin} - 15	TCL _{Hmin} + 15	ns
Data valid to WR transition	t_{QVWX}	5	_	TCL _{Lmin} - 20	_	ns
Data setup before WR	t _{QVWH}	163	-	3 CLP + TCL _{Lmin} - 50	_	ns
Data hold after WR	t_{WHQX}	5	_	TCL _{Hmin} - 20	_	ns
Address float after RD	t_{RLAZ}	_	0	_	0	ns

Data Sheet 69 12.00



AC Characteristics (16 MHz, 0.4 to 0.6 Duty Cycle, cont'd)

External Clock Drive Characteristics

Parameter	Symbol	CPU Clock = 16 MHz Duty Cycle 0.4 to 0.6		Variable (1/CLP = 2	Unit	
		min.	max.	min.	max.	
Oscillator period	CLP	62.5	62.5	62.5	500	ns
High time	TCL _H	25	_	25	CLP - TCL _L	ns
Low time	TCL	25	_	25	CLP - TCL _H	ns
Rise time	t_{R}	_	10	_	10	ns
Fall time	t_{F}	_	10	_	10	ns
Oscillator duty cycle	DC	0.4	0.6	25 / CLP	1 - 25 / CLP	_
Clock cycle	TCL	25	37.5	CLP * DC _{min}	CLP * DC _{max}	ns

Note: The 16 MHz values in the tables are given as an example for a typical duty cycle variation of the oscillator clock from 0.4 to 0.6.

Data Sheet 70 12.00



AC Characteristics (20 MHz, 0.5 Duty Cycle)

(Operating Conditions apply)

(C_L for port 0, ALE and $\overline{\text{PSEN}}$ outputs = 100 pF; C_L for all other outputs = 80 pF)

Program Memory Characteristics

Parameter	Symbol		Limit Values					
		20 MHz clock 0.5 Duty Cycle		Variable Clock 1/CLP = 2 MHz to 20 MHz				
		min.	max.	min.	max.			
ALE pulse width	t_{LHLL}	35	_	CLP - 15	_	ns		
Address setup to ALE	t_{AVLL}	10	_	CLP/2 - 15	_	ns		
Address hold after ALE	t_{LLAX}	10	_	CLP/2 - 15	_	ns		
ALE to valid instruction in	t_{LLIV}	_	55	_	2 CLP - 45	ns		
ALE to PSEN	t_{LLPL}	10	_	CLP/2 - 15	_	ns		
PSEN pulse width	t_{PLPH}	60	_	3/2 CLP - 15	_	ns		
PSEN to valid instruction in	t_{PLIV}	_	25	_	3/2 CLP - 50	ns		
Input instruction hold after PSEN	t_{PXIX}	0	_	0	_	ns		
Input instruction float after PSEN	t _{PXIZ} *)	_	20	_	CLP/2 - 5	ns		
Address valid after PSEN	t _{PXAV} *)	20	_	CLP/2 - 5	_	ns		
Address to valid instruction in	t_{AVIV}	_	65	_	5/2 CLP - 60	ns		
Address float to PSEN	t_{AZPL}	- 5	_	- 5	_	ns		

^{*)} Interfacing the C505 to devices with float times up to 20 ns is permissible. This limited bus contention will not cause any damage to port 0 drivers.

Data Sheet 71 12.00



AC Characteristics (20 MHz, 0.5 Duty Cycle, cont'd)

External Data Memory Characteristics

Parameter	Symbol	Limit Values				
		20 MHz clock 0.5 Duty Cycle		Variable Clock 1/CLP = 2 MHz to 20 MHz		
		min.	max.	min.	max.	
RD pulse width	t_{RLRH}	120	_	3 CLP - 30	_	ns
WR pulse width	t _{WLWH}	120	_	3 CLP - 30	_	ns
Address hold after ALE	t _{LLAX2}	35	_	CLP - 15	_	ns
RD to valid data in	t_{RLDV}	_	75	_	5/2 CLP- 50	ns
Data hold after RD	t_{RHDX}	0	_	0	_	ns
Data float after RD	t_{RHDZ}	_	38	_	CLP - 12	ns
ALE to valid data in	t_{LLDV}	_	150	_	4 CLP - 50	ns
Address to valid data in	t_{AVDV}	_	150	_	9/2 CLP - 75	ns
ALE to WR or RD	t_{LLWL}	60	90	3/2 CLP - 15	3/2 CLP + 15	ns
Address valid to WR	t _{AVWL}	70	_	2 CLP - 30	_	ns
WR or RD high to ALE high	t _{WHLH}	10	40	CLP/2 - 15	CLP/2 + 15	ns
Data valid to WR transition	t_{QVWX}	5	_	CLP/2 - 20	_	ns
Data setup before WR	t_{QVWH}	125	_	7/2 CLP - 50	_	ns
Data hold after WR	t_{WHQX}	5	_	CLP/2 - 20	_	ns
Address float after RD	t_{RLAZ}	_	0	_	0	ns

External Clock Drive Characteristics

Parameter	Symbol		Unit	
		Freq		
		min.	max.	
Oscillator period	CLP	50	500	ns
High time	TCL _H	15	CLP-TCL _L	ns
Low time	TCLL	15	CLP-TCL _H	ns
Rise time	t_{R}	_	10	ns
Fall time	t _F	_	10	ns
Oscillator duty cycle	DC	0.5	0.5	_

Data Sheet 72 12.00



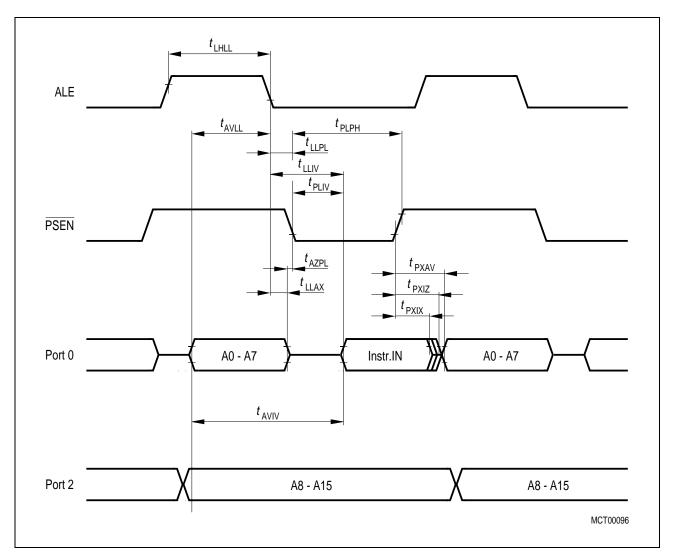


Figure 32 Program Memory Read Cycle

Data Sheet 73 12.00



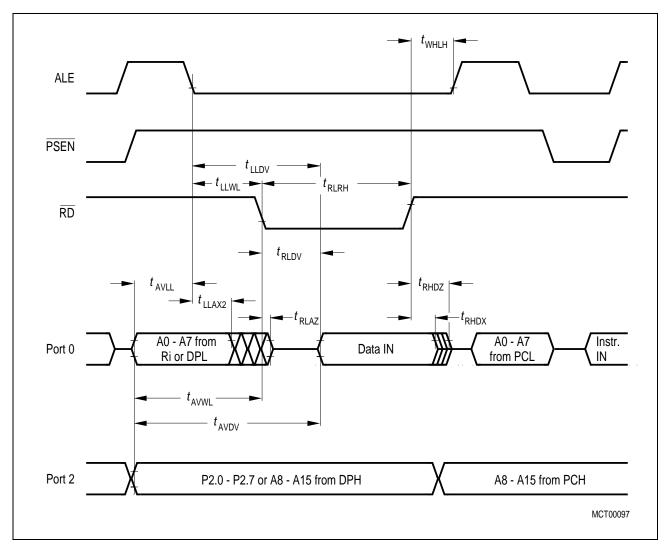


Figure 33
Data Memory Read Cycle

Data Sheet 74 12.00



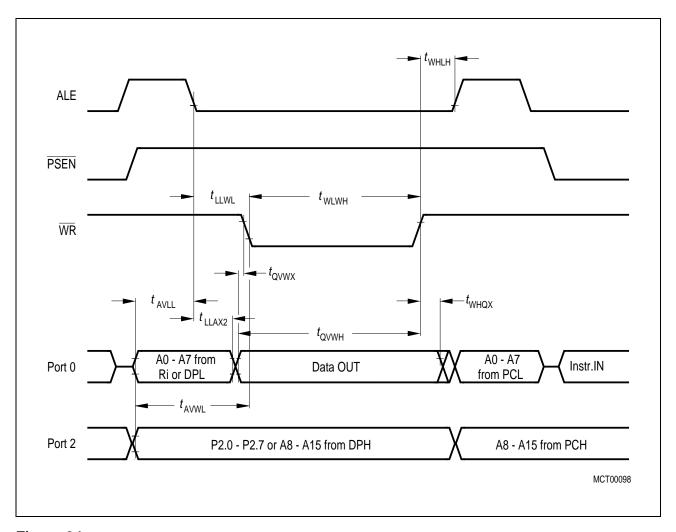


Figure 34
Data Memory Write Cycle

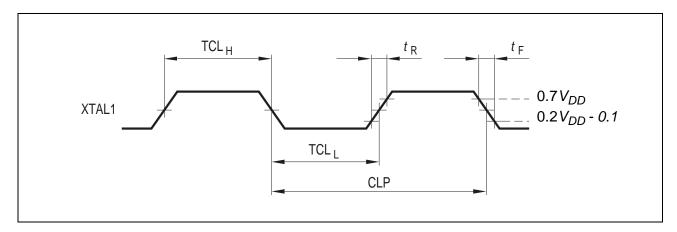


Figure 35
External Clock Drive on XTAL1

Data Sheet 75 12.00



AC Characteristics of Programming Mode (C505A-4E and C505CA-4E only)

 $V_{\rm DD}$ = 5 V \pm 10 %; $V_{\rm PP}$ = 11.5 V \pm 5 %; $T_{\rm A}$ = 25 °C \pm 10 °C

Parameter	Symbol	L	imit Values	Unit
		min.	max.	
PALE pulse width	t_{PAW}	35	_	ns
PMSEL setup to PALE rising edge	t_{PMS}	10	_	
Address setup to PALE, PROG, or PRD falling edge	t_{PAS}	10	-	ns
Address hold after PALE, PROG, or PRD falling edge	t_{PAH}	10	_	ns
Address, data setup to PROG or PRD	t_{PCS}	100	_	ns
Address, data hold after PROG or PRD	t_{PCH}	0	_	ns
PMSEL setup to PROG or PRD	t_{PMS}	10	_	ns
PMSEL hold after PROG or PRD	t_{PMH}	10	_	ns
PROG pulse width	t_{PWW}	100	_	μs
PRD pulse width	t_{PRW}	100	_	ns
Address to valid data out	t_{PAD}	_	75	ns
PRD to valid data out	t_{PRD}	_	20	ns
Data hold after PRD	t_{PDH}	0	_	ns
Data float after PRD	t_{PDF}	_	20	ns
PROG high between two consecutive PROG low pulses	t _{PWH1}	1	-	μs
PRD high between two consecutive PRD low pulses	t _{PWH2}	100		ns
XTAL clock period	t_{CLKP}	83.3	500	ns

Data Sheet 76 12.00



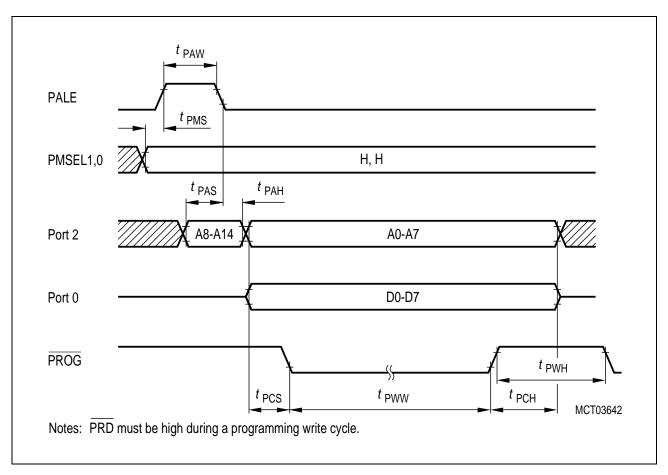


Figure 36
Programming Code Byte - Write Cycle Timing

Data Sheet 77 12.00



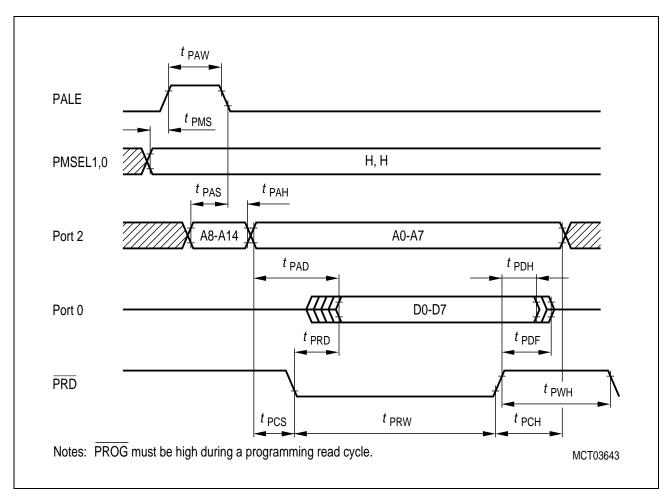


Figure 37 Verify Code Byte - Read Cycle Timing

Data Sheet 78 12.00



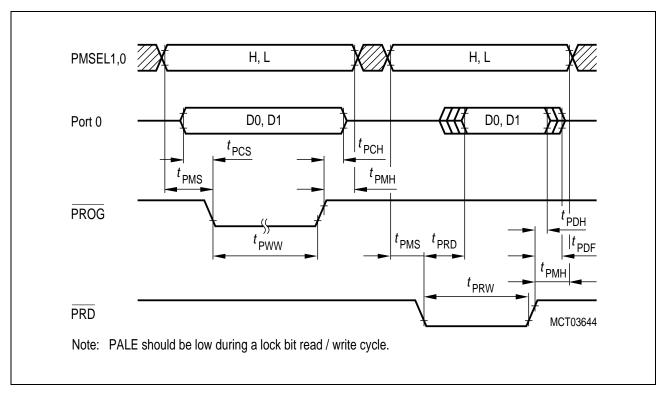


Figure 38 Lock Bit Access Timing

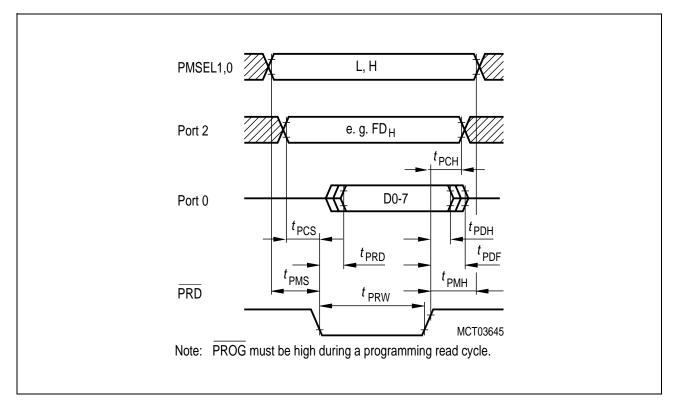


Figure 39 Version Byte Read Timing

Data Sheet 79 12.00



ROM/OTP Verification Characteristics for C505

ROM Verification Mode 1 (C505(C)(A)-2R and C505(C)A-4R only)

Parameter	Symbol	Limit '	Unit	
		min.	max.	
Address to valid data	t_{AVQV}	_	5 CLP	ns

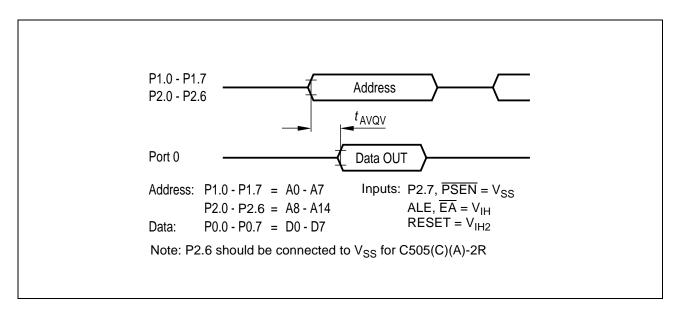


Figure 40 ROM Verification Mode 1

Data Sheet 80 12.00



ROM/OTP Verification Characteristics for C505 (cont'd)

ROM/OTP Verification Mode 2

Parameter	Symbol		Limit Values		Unit
		min.	typ	max.	
ALE pulse width	t_{AWD}	_	CLP	_	ns
ALE period	t_{ACY}	_	6 CLP	_	ns
Data valid after ALE	t_{DVA}	_	_	2 CLP	ns
Data stable after ALE	t_{DSA}	4 CLP	_	_	ns
P3.5 setup to ALE low	t_{AS}	_	t_{CL}	_	ns
Oscillator frequency	1/ CLP	4	_	6	MHz

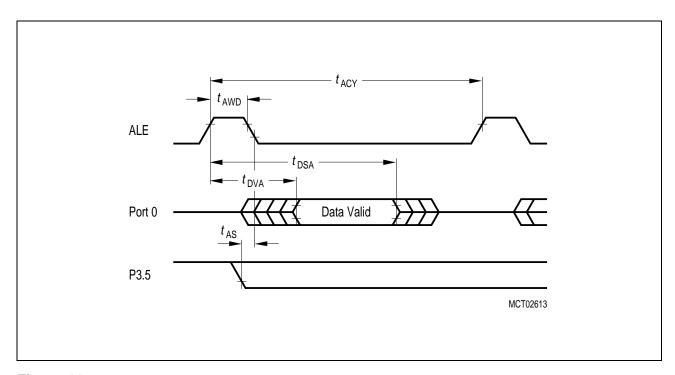
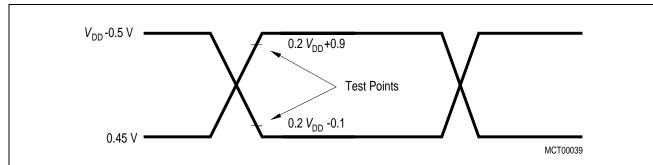


Figure 41 ROM/OTP Verification Mode 2

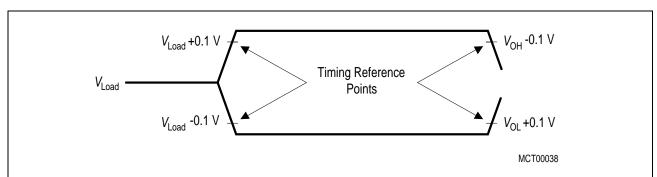
Data Sheet 81 12.00





AC Inputs during testing are driven at $V_{\rm DD}$ - 0.5 V for a logic '1' and 0.45 V for a logic '0'. Timing measurements are made at $V_{\rm IHmin}$ for a logic '1' and $V_{\rm ILmax}$ for a logic '0'.

Figure 42 AC Testing: Input, Output Waveforms



For timing purposes a port pin is no longer floating when a 100 mV change from load voltage occurs and begins to float when a 100 mV change from the loaded $V_{\rm OH}/V_{\rm OL}$ level occurs. $I_{\rm OL}/I_{\rm OH} \ge \pm$ 20 mA

Figure 43 AC Testing : Float Waveforms

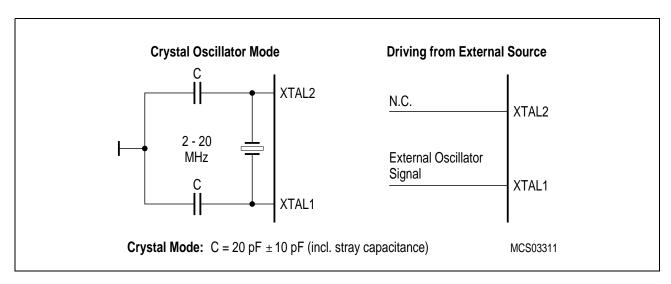


Figure 44
Recommended Oscillator Circuits for Crystal Oscillator

Data Sheet 82 12.00



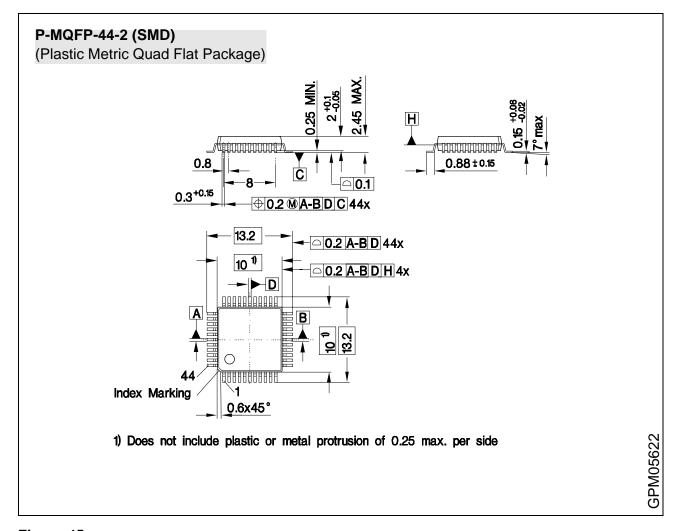


Figure 45 P-MQFP-44 Package Outline

Sorts of Packing

Package outlines for tubes, trays etc. are contained in our Data Book "Package Information"

SMD = Surface Mounted Device

Dimensions in mm

Infineon goes for Business Excellence

"Business excellence means intelligent approaches and clearly defined processes, which are both constantly under review and ultimately lead to good operating results.

Better operating results and business excellence mean less idleness and wastefulness for all of us, more professional success, more accurate information, a better overview and, thereby, less frustration and more satisfaction."

Dr. Ulrich Schumacher

http://www.infineon.com